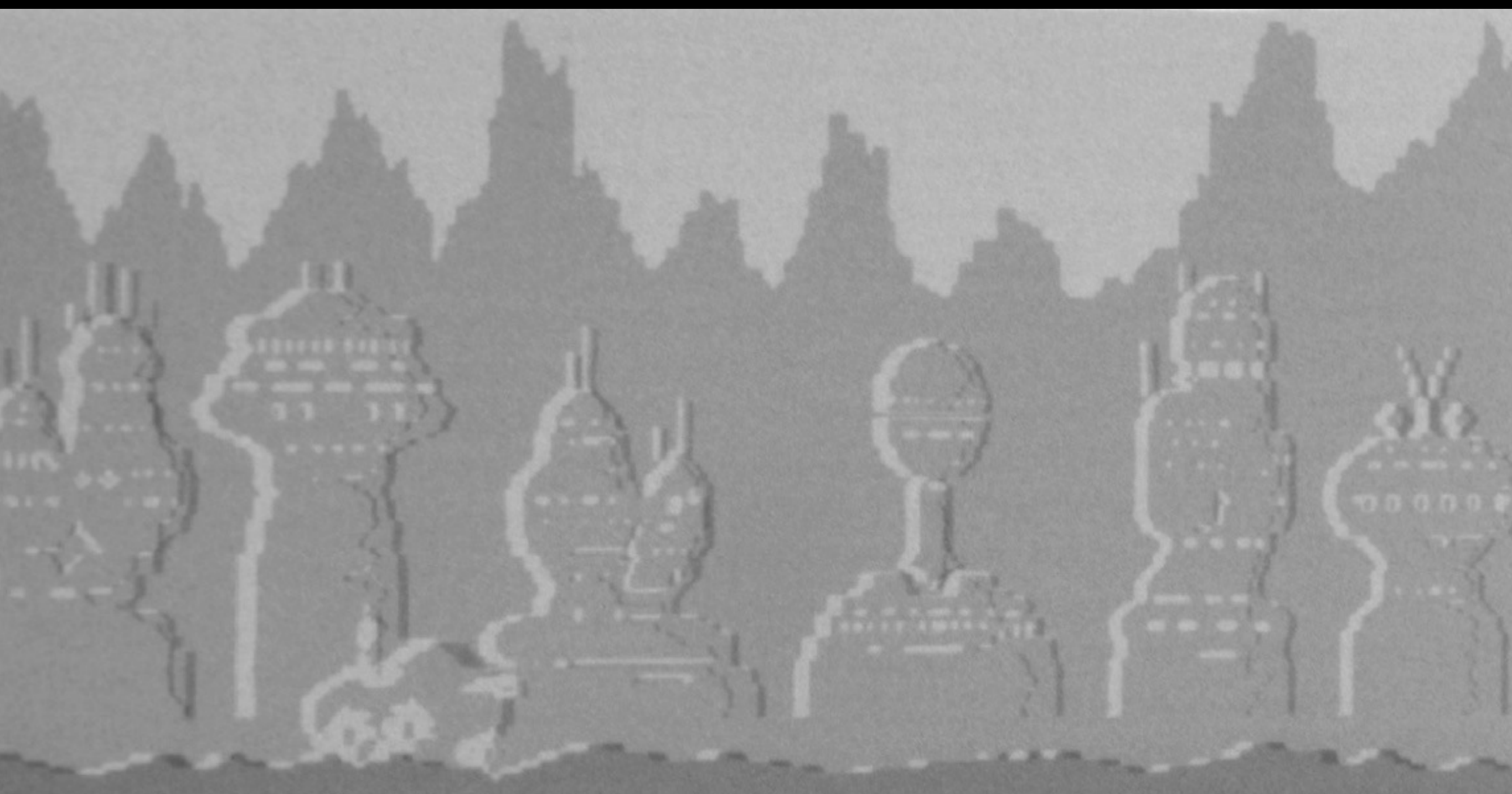


Deconstructing the Circuit Board Sandwich: Effective Techniques for PCB Reverse Engineering



Joe Grand (@joegrand)
Grand Idea Studio, Inc.

PCB Reverse Engineering

- The art of "undesigning" an existing system
- Destructive and non-destructive methods
- Why?
 - Determine system or subsystem functionality
 - Security research/verification
 - Forensic analysis/intelligence
 - Clone a design
 - Inject new (malicious) behavior
- How?
 - Access to copper layers
 - Analyze layout rules/features
 - Trace component interconnections

Deconstruction Techniques

- Solder Mask Removal
- Delayering
- Imaging

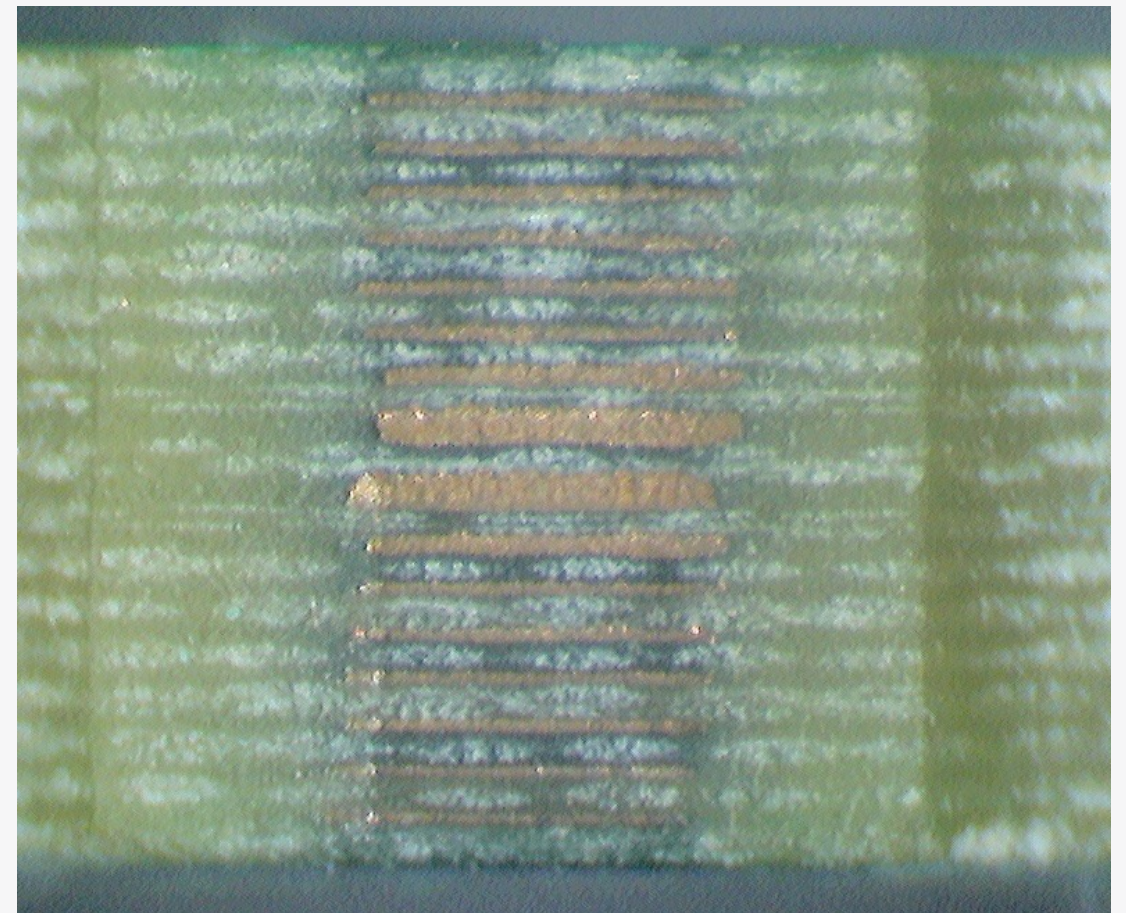
* Results of my DARPA CFT *Research and Analysis of PCB Deconstruction Techniques* project, www.grandideastudio.com/portfolio/pcbdt/

PCB Construction & Layer Stack

- Layers of thin copper foil (conductive) laminated to insulating (non-conductive) layers
 - "Circuit board sandwich"
- Form the physical carrier and electrical pathways for components



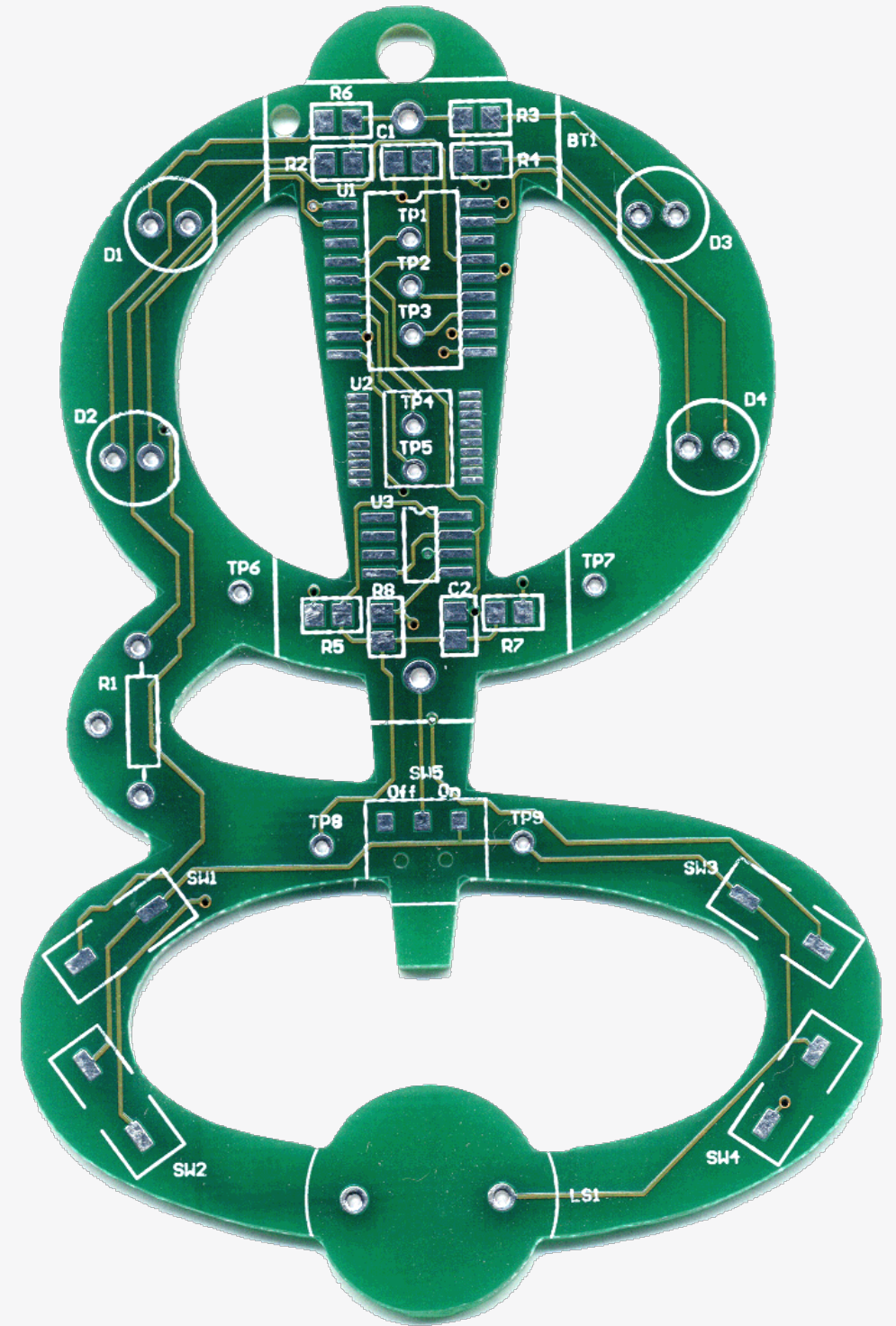
Spekkoek (not a PCB)



PCB cross-section (16 layer)

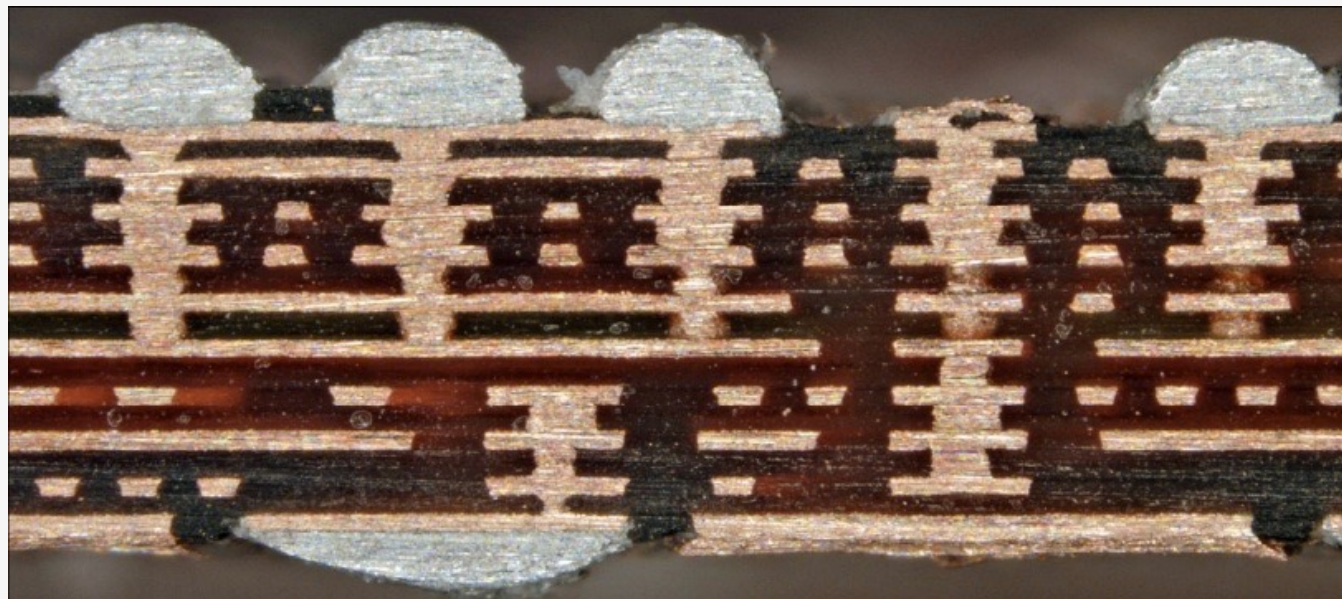
PCB Construction & Layer Stack 2

- Silkscreen (Component Legend)
 - Epoxy or printable ink
 - Part designators, symbols/logos, manufacturing/test markings
- Soldermask
 - Protects PCB from dust/moisture
 - Provides access to desired copper areas
- Copper
 - Thickness = weight of copper/sq. ft.
 - Surface finish provides better solderability
- Substrate
 - Insulating layer
 - Rigid and/or flex, fiberglass/epoxy weave or specialized composite



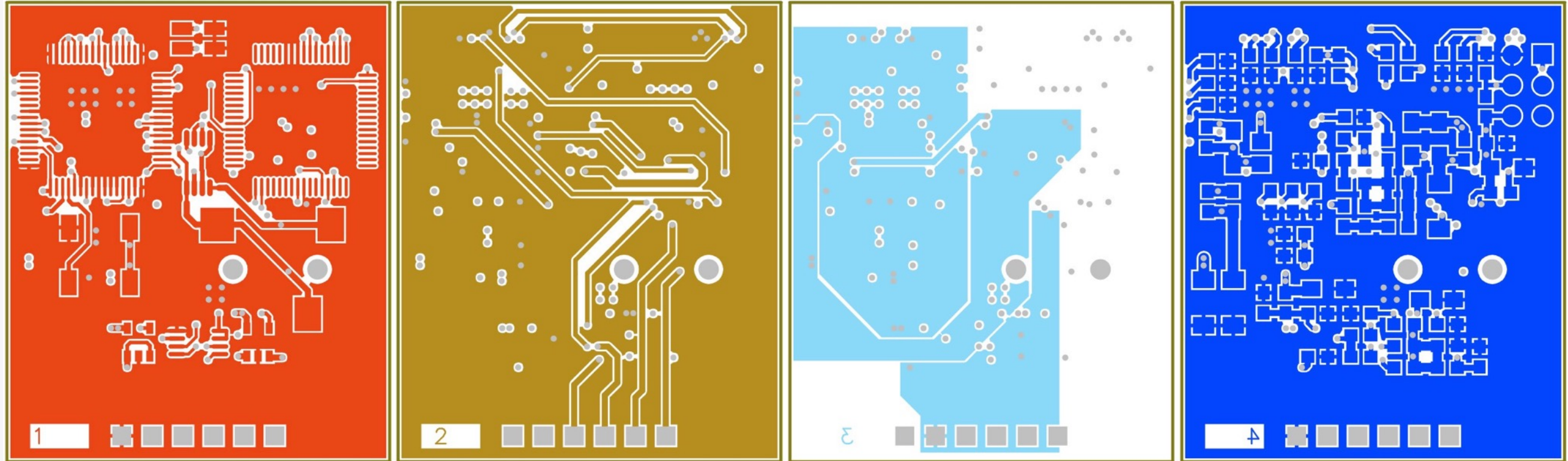
PCB Construction & Layer Stack 3

- Traditional capabilities
 - 3 mil trace/space width
 - 8 mil diameter mechanically-drilled vias
 - Buried vias
- State-of-the art capabilities
 - < 1 mil trace/space width
 - 0.4 mil diameter laser-drilled microvia
 - Via-in-pad



PCB Construction & Layer Stack 4

- Separate layers only tell part (if any) of the story
- Placed together, a complete circuit layout can be identified
- If components are also known, a full electrical design can be reversed



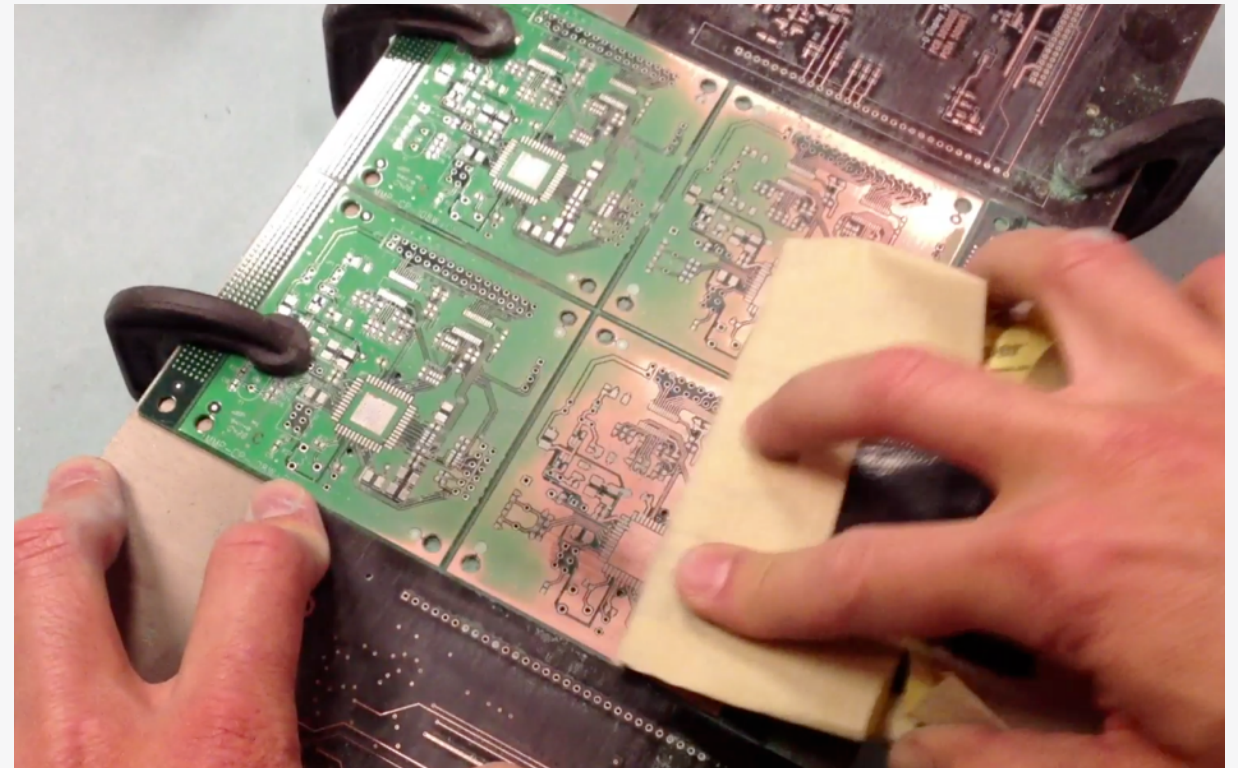
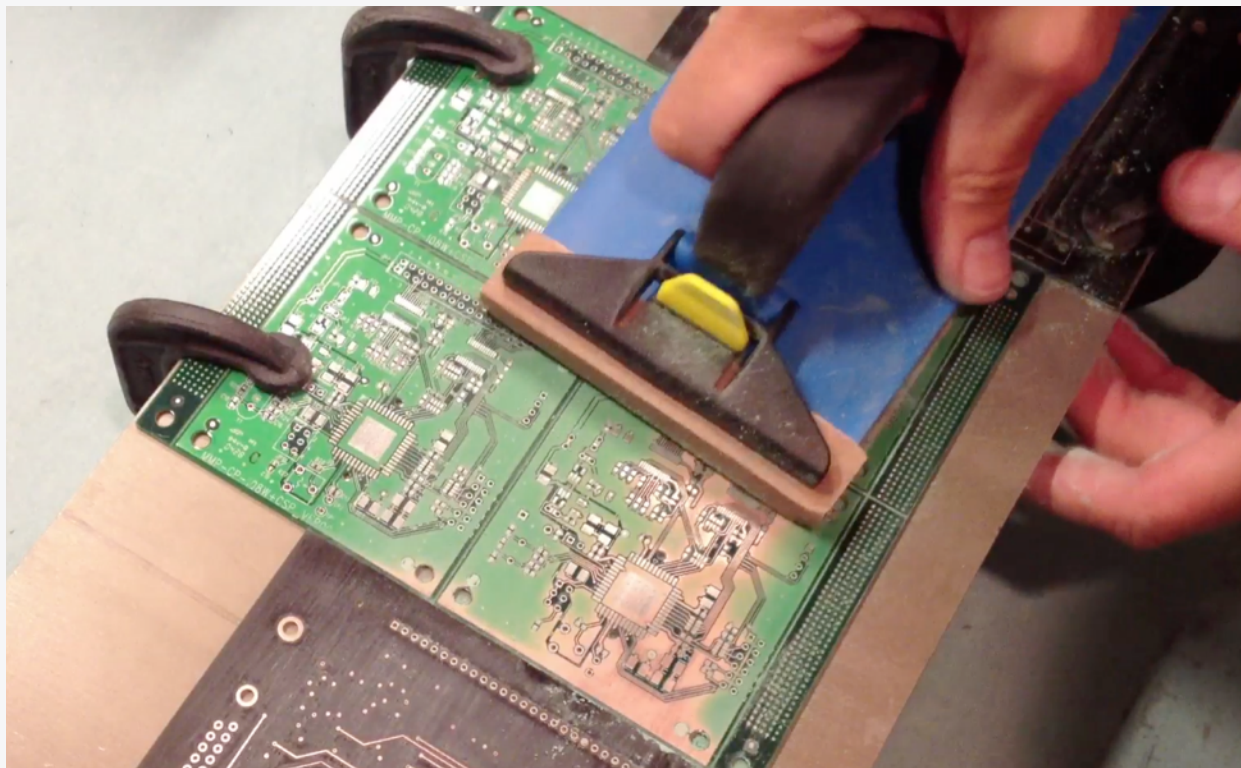
Emic 2 Text-to-Speech Module

Solder Mask Removal

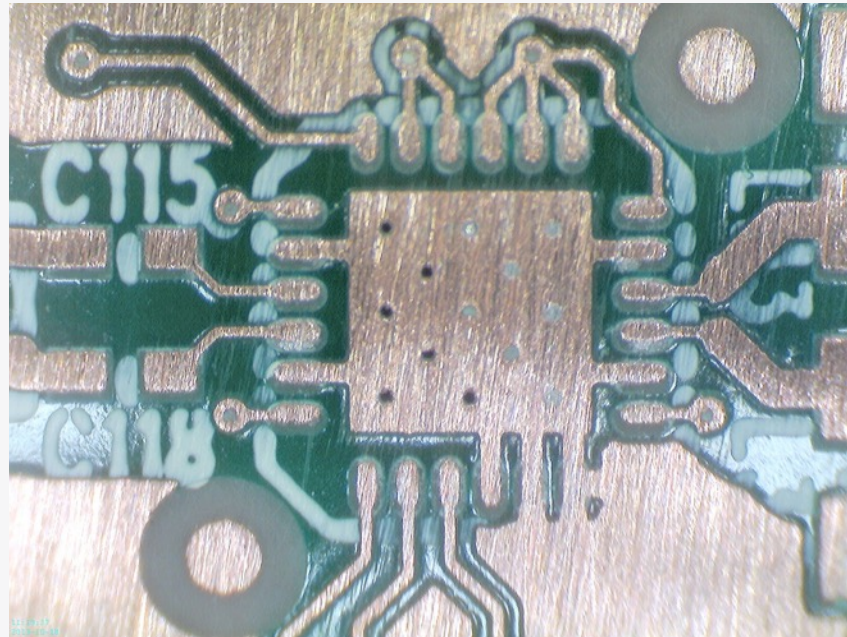
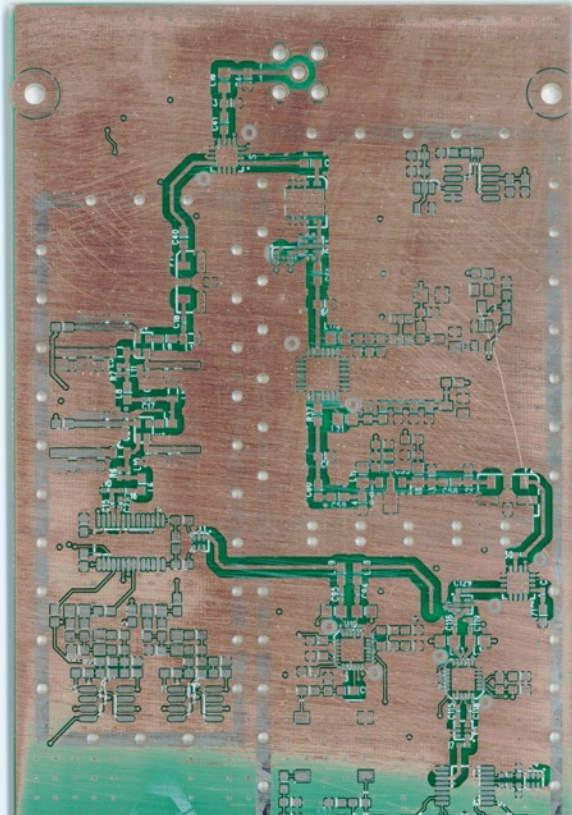
- Sandpaper/rubbing stone
- Fiberglass scratch brush
- Abrasive sand blasting
- Chemical
- Laser

Solder Mask Removal: Sandpaper/Rubbing Stone

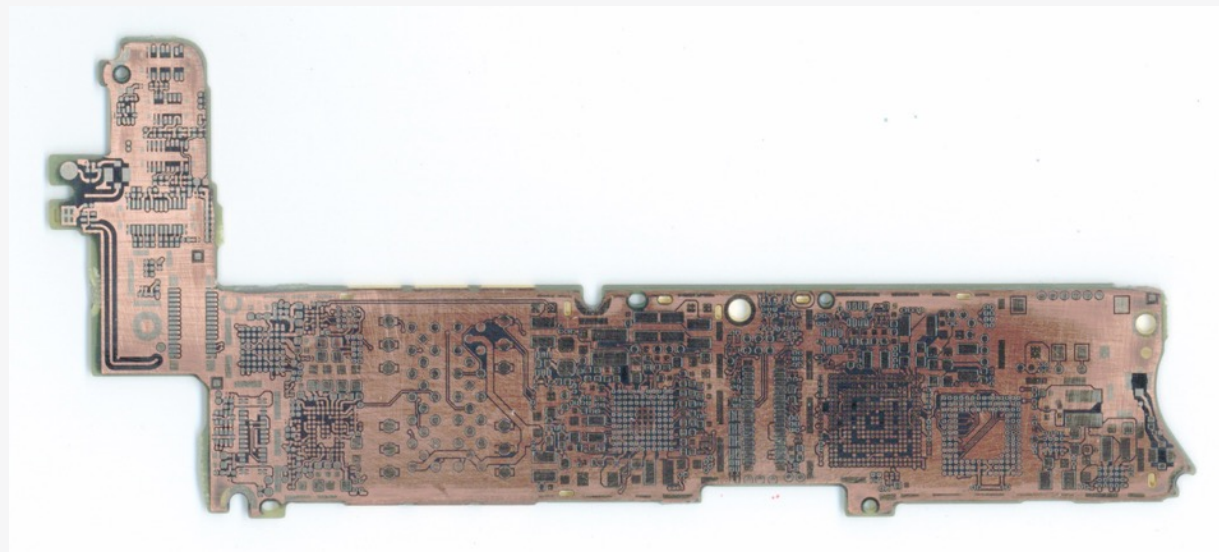
- Effective, lowest cost method
- Even strokes across the entire PCB @ light pressure
- Spare PCBs of same height used on sides to help maintain planar motion
- Different PCB surface finishes require different grit sizes
- Excessive abrasion can cause damage to underlying copper



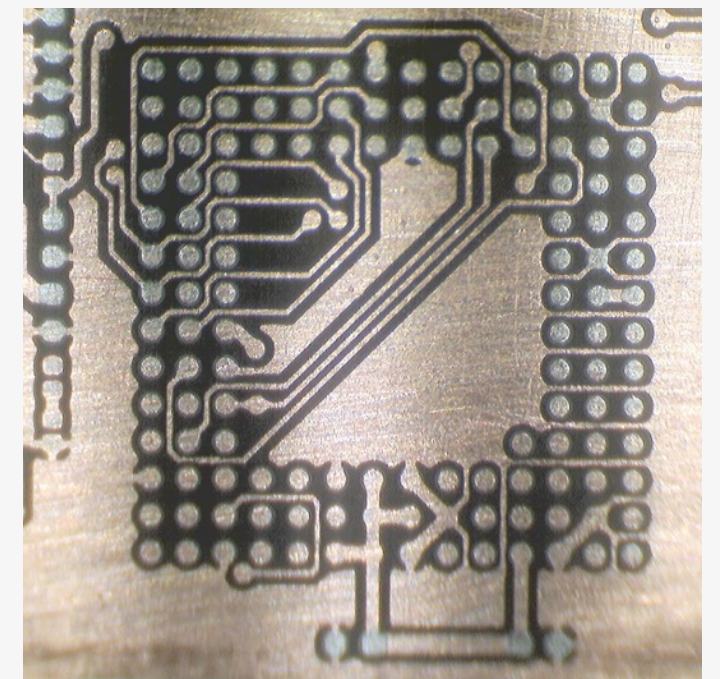
Solder Mask Removal: Sandpaper/Rubbing Stone 2



60/80 grit rubbing stone +
220 grit sandpaper

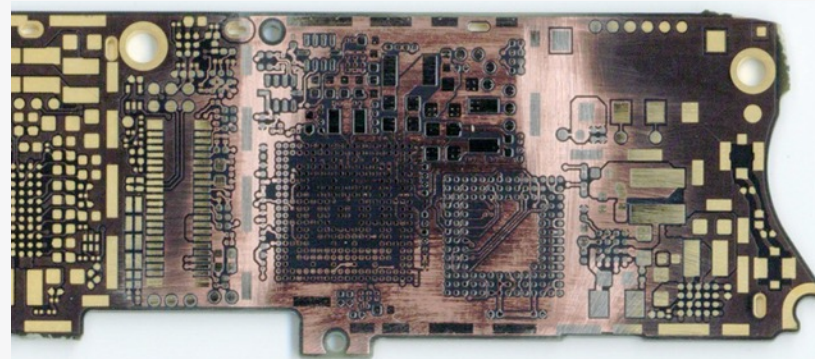
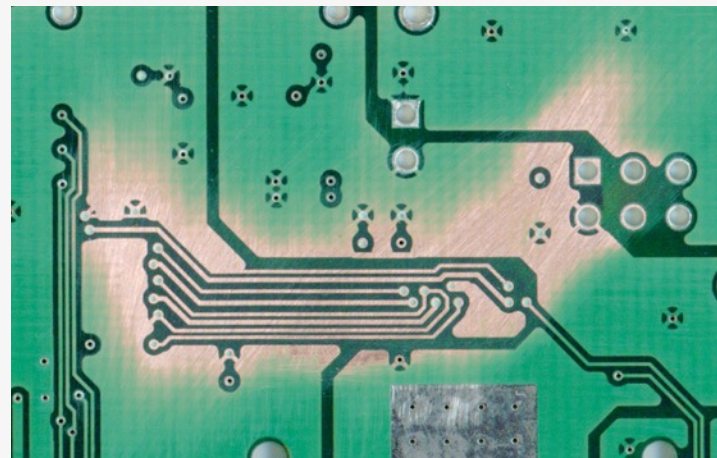
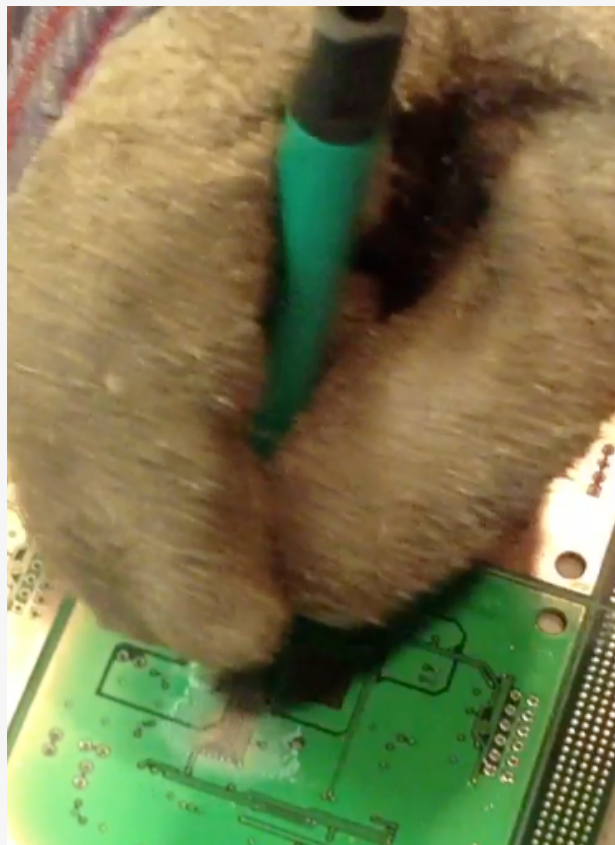


iPhone 4 16GB w/ 400 grit sandpaper



Solder Mask Removal: Fiberglass Scratch Brush

- Handheld, pencil-shaped tool for material cleaning/polishing
- Excelta/Eurotool 267
- Very nice result w/ only light wearing of copper
- Precise control also useful for selective, small area mask removal
- BOLO: Fiberglass shards can/will get stuck in your hands



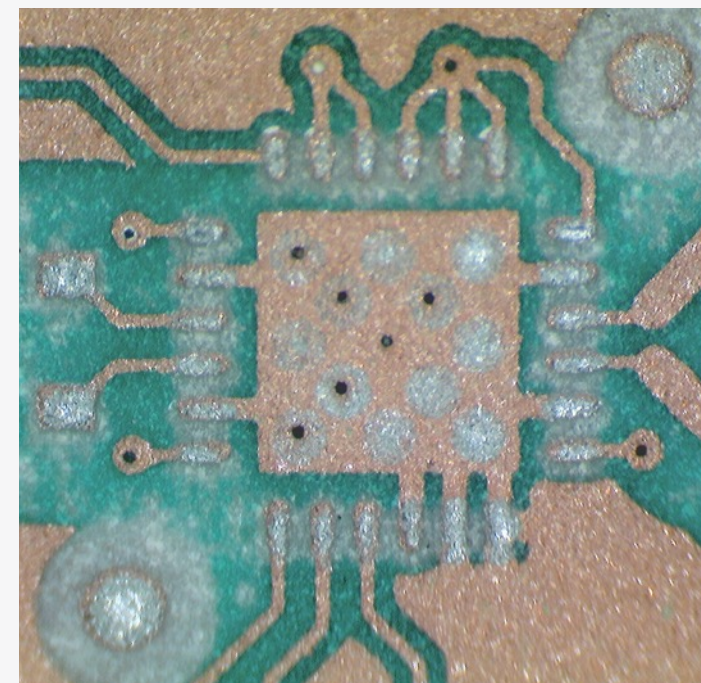
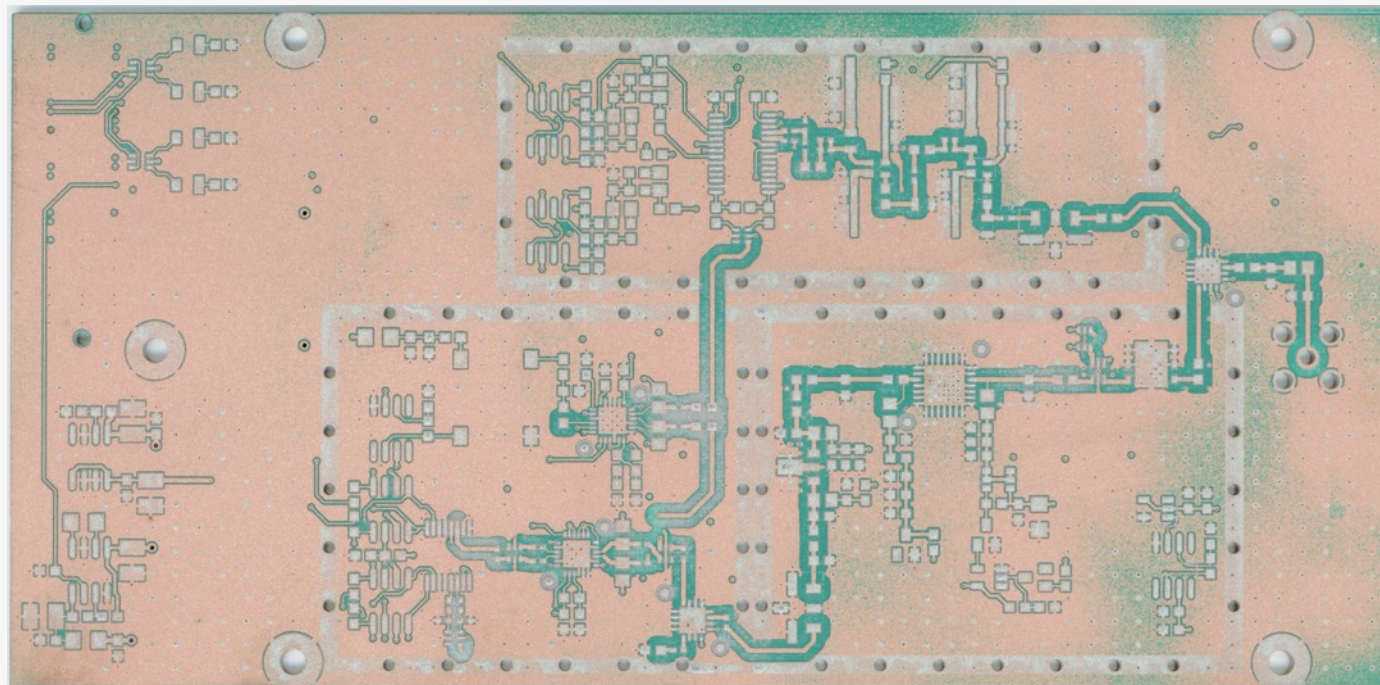
Solder Mask Removal: Abrasive Sand Blasting

- Typically used to strip material from surfaces (paint, calcium deposits, fungus) or add texture/artificial wear
- TP Tools Skat Blast 1536 Champion Blast Cabinet @ TechShop, San Francisco, CA
- Best results w/ nozzle angled & held 6-8" away from PCB surface



Solder Mask Removal: Abrasive Sand Blasting 2

- 60# aluminum oxide @ 80PSI (pounds/sq in), 10-15 CFM (cubic ft/min)
- Noticeable pitting, but copper and substrate remained intact
 - Softer media (crushed walnut shells) may cause less surface wear
 - Risk of damage by focusing on one area of PCB for too long
- Best suited for PCBs w/ trace/space \geq 10/10mil & copper weight \geq 1oz (1.4mil)



Solder Mask Removal: Chemical

- Typically used by PCB fabricators for failure analysis or to fix a manufacturing error
- BOLO: Requires hazardous chemical handling and disposal procedures



* Not a meth lab.

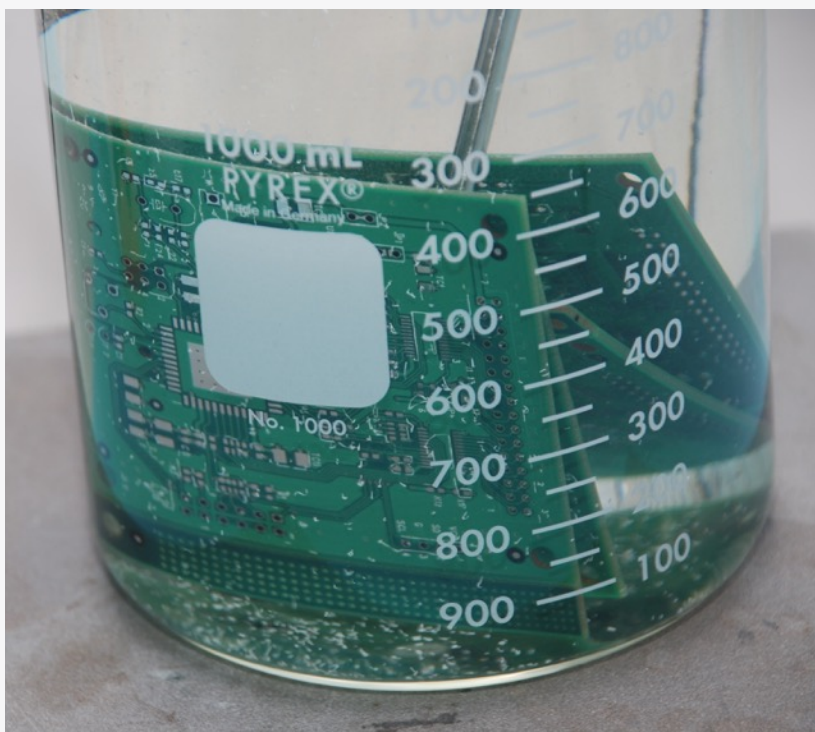
Solder Mask Removal: Chemical 2



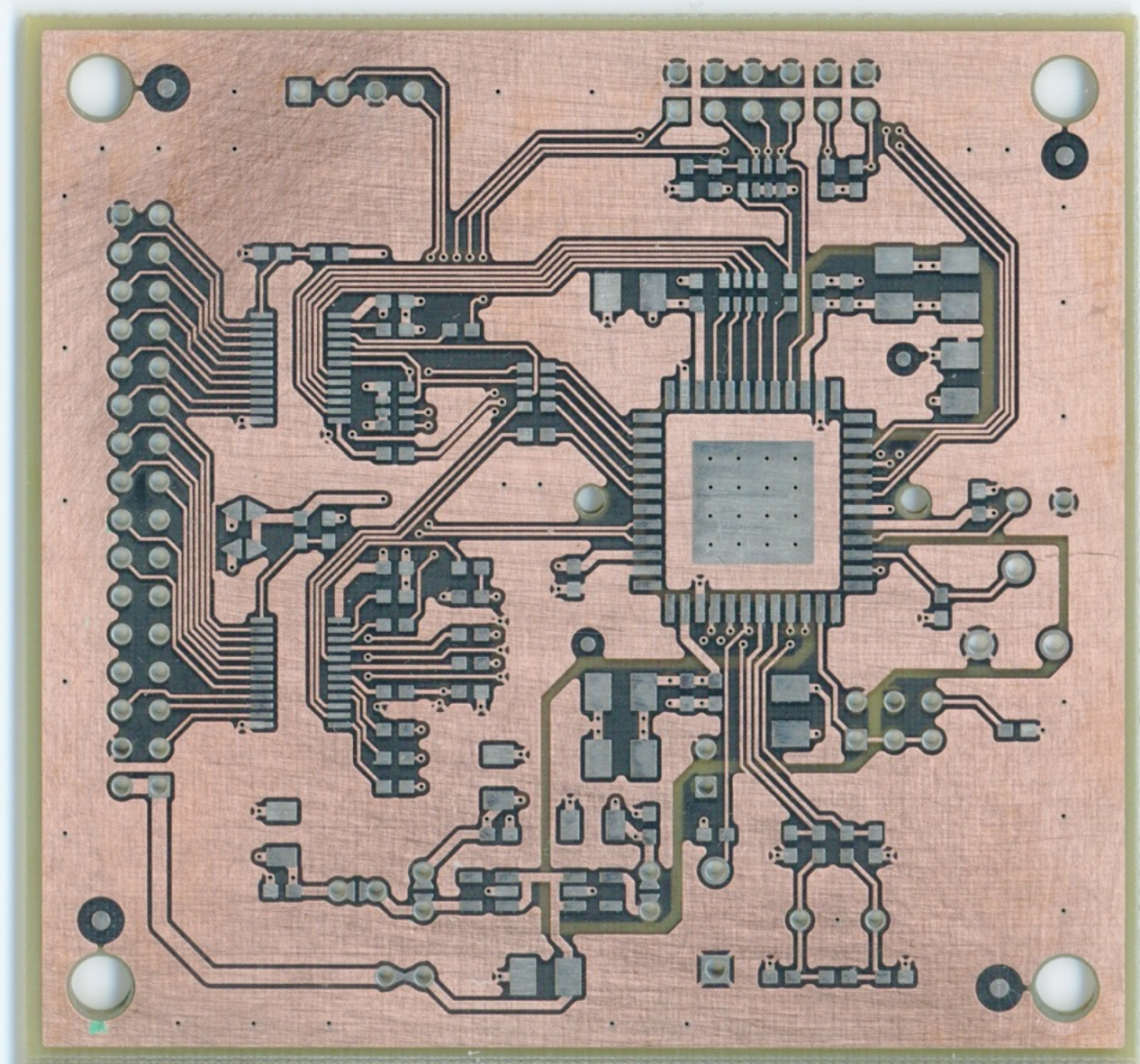
* Not a meth dealer.

Solder Mask Removal: Chemical 3

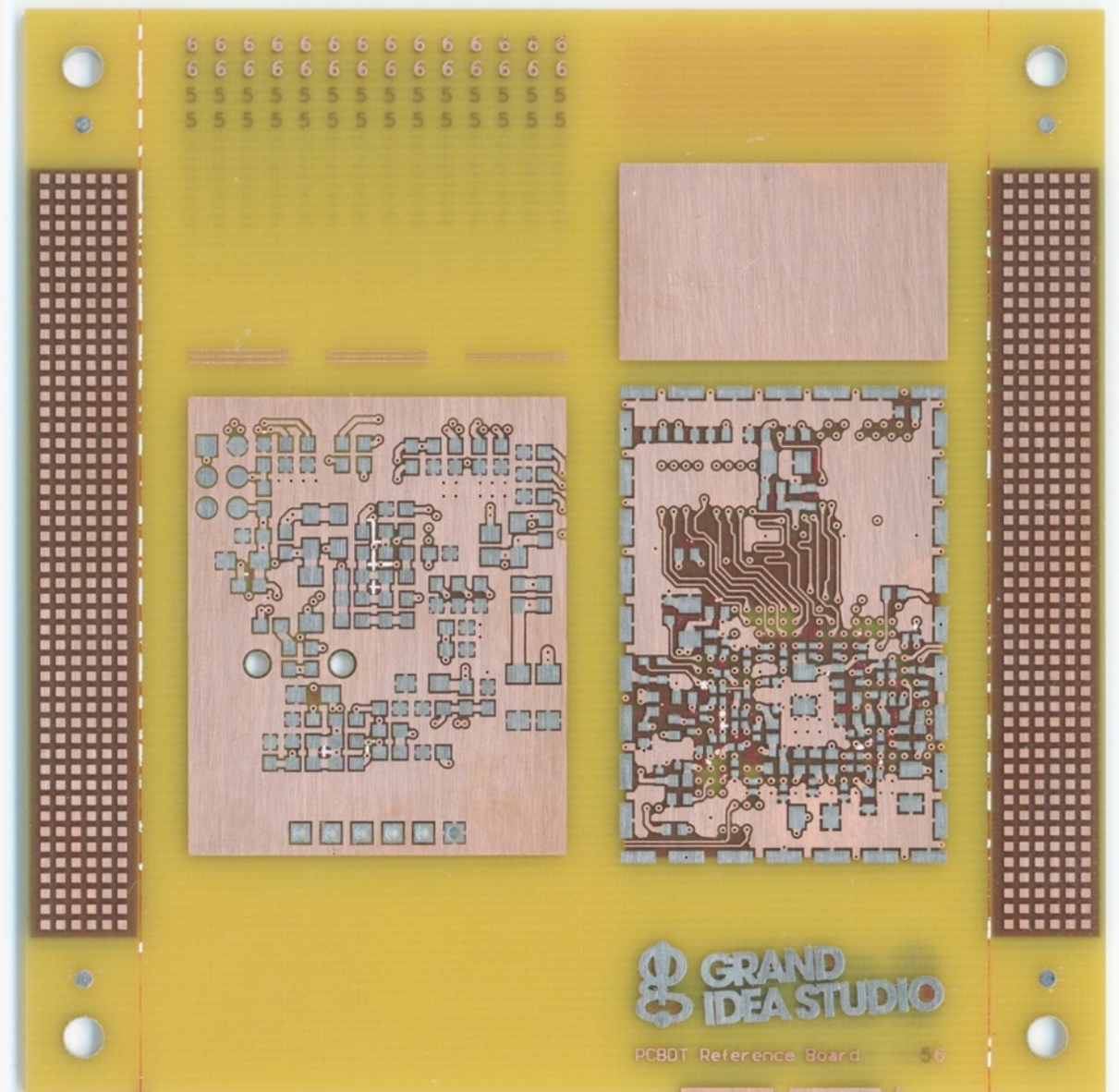
- Ristoff C-8 (NWE Chem Research, UK)
- Magnastrip 500 (RBP Chemical Technology, US)
- Neither chemical will attack the PCB substrate/laminate
- Heat chemical, soak PCB, rinse in water & brush lightly w/ soft metal brush
 - Processing time (~45-120 minutes) varies due to chemical temperature, solder mask composition, and solder mask thickness



Solder Mask Removal: Chemical 4



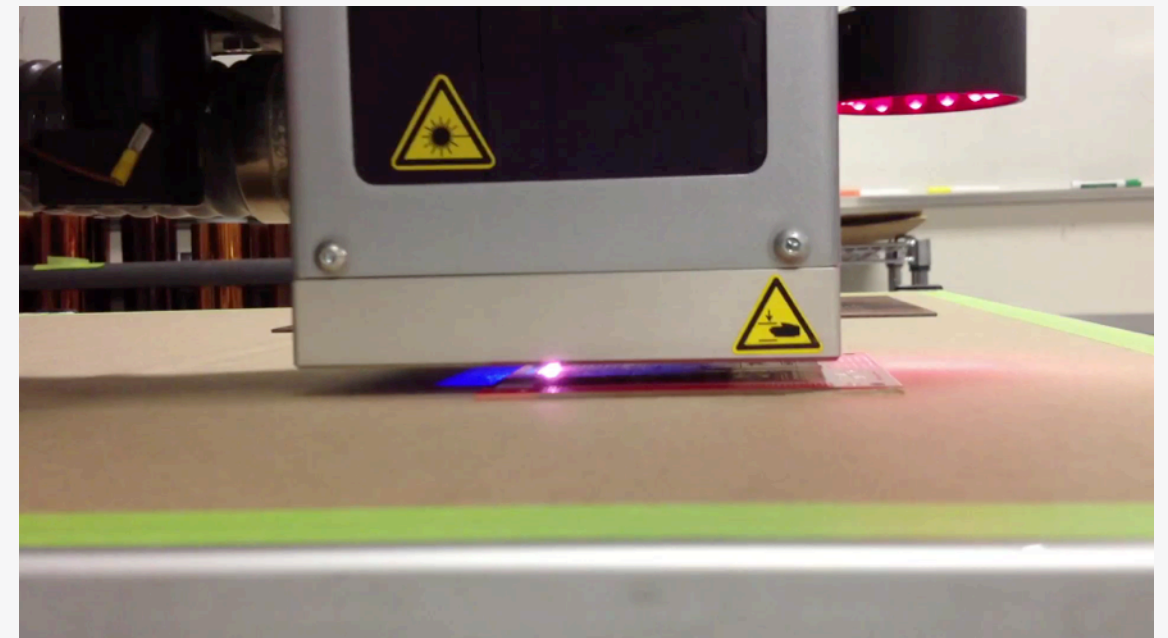
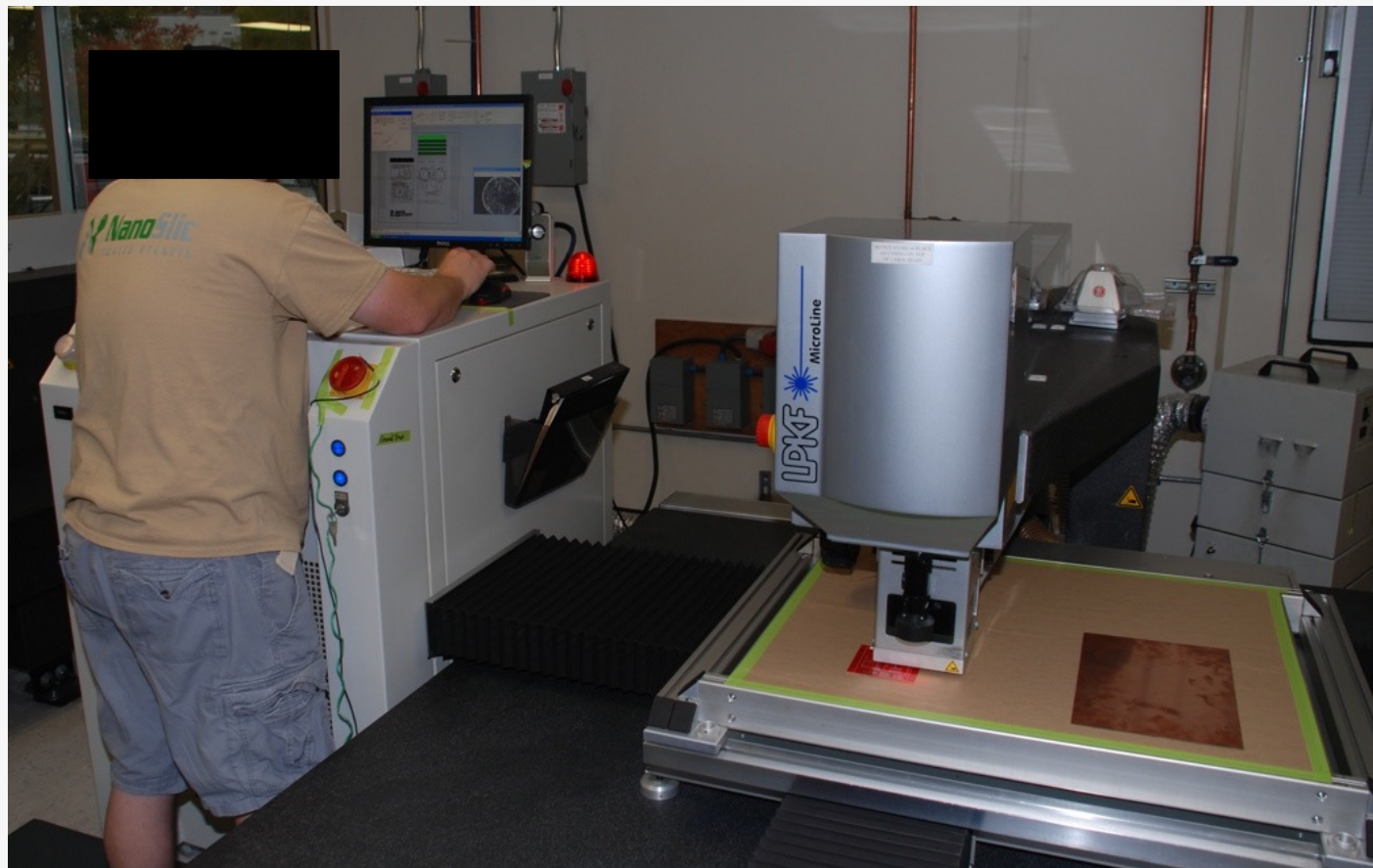
Ristoff C-8 @ 90 minutes, 130°F



Magnastrip 500 @ 75 minutes, 150°F

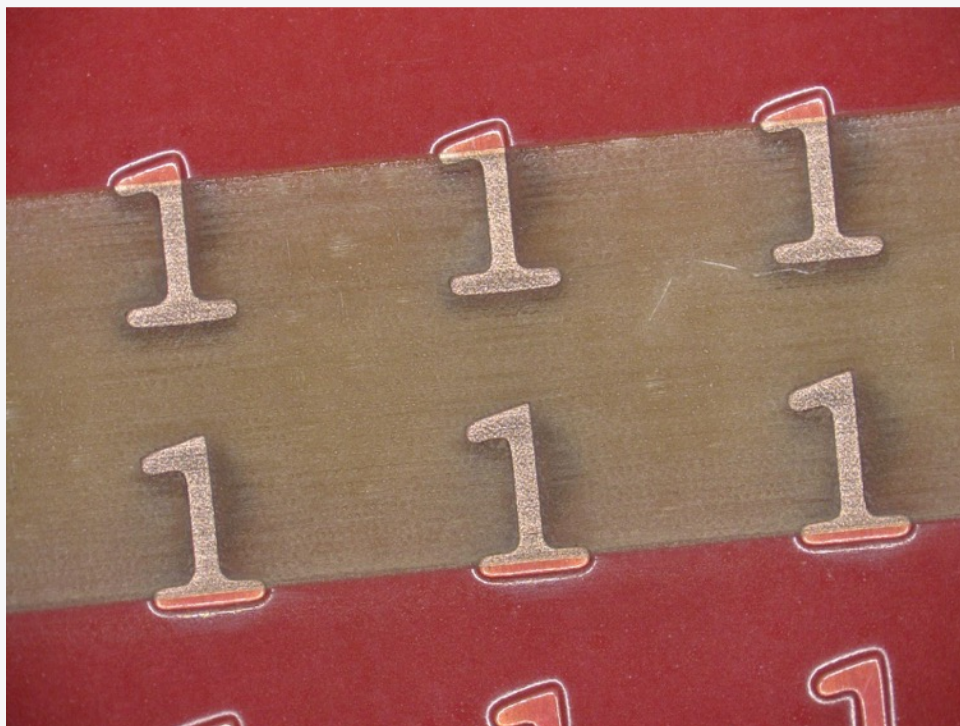
Solder Mask Removal: Laser

- LPKF MicroLine 600D UV Laser System @ A-Laser, Milpitas, CA
- Typically used for cutting of flex circuits and coverlayer material (film, foil, adhesive)
- +/-0.6 mil accuracy, 300mm/sec. (11.8"/sec.) max. travel speed, 20um (0.787mil) beam diameter

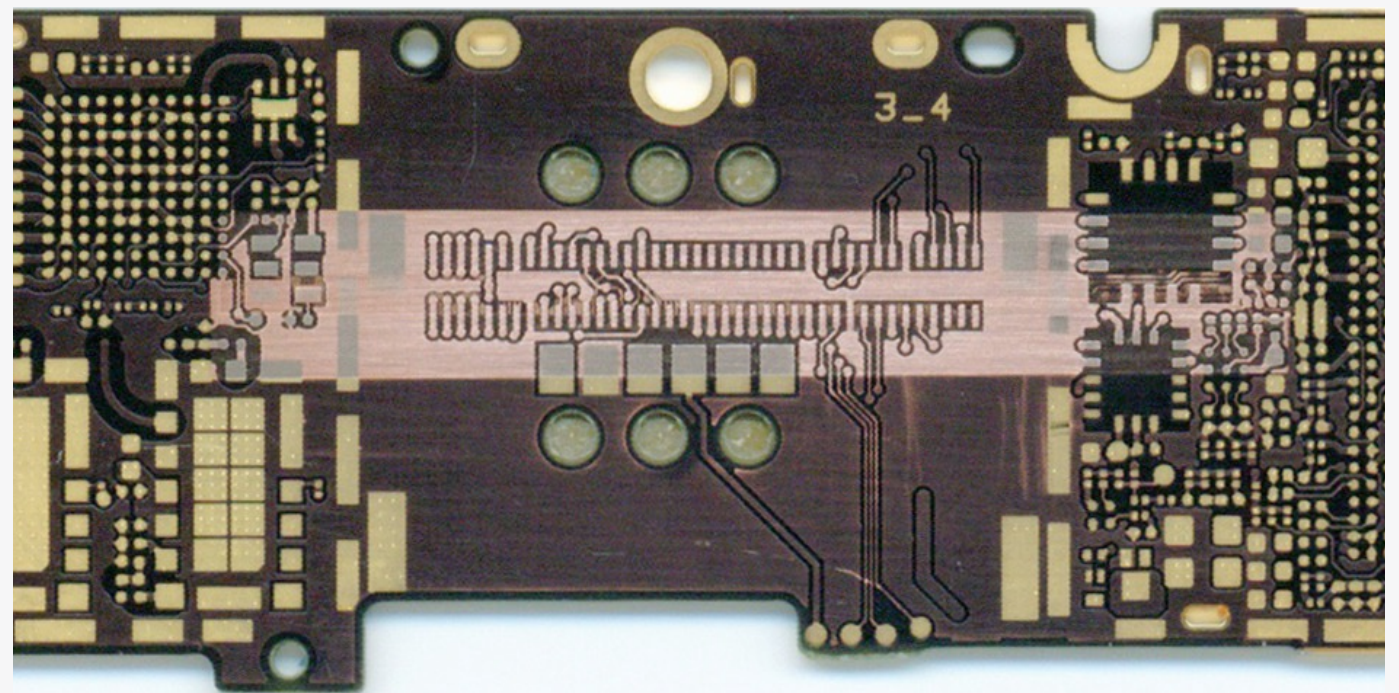


Solder Mask Removal: Laser 2

- Single pass @ medium power
- Copper layer remains fully intact
- Different materials react differently to the laser energy
 - Solder mask and FR4 ablate more quickly than copper
 - Incorrect laser power settings or too many passes can damage underlying copper



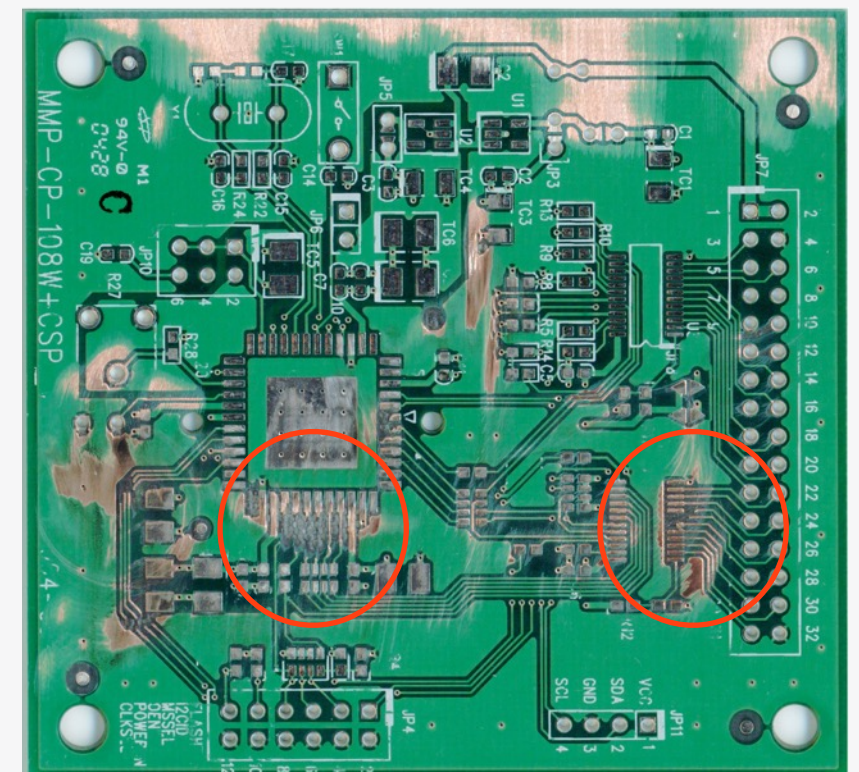
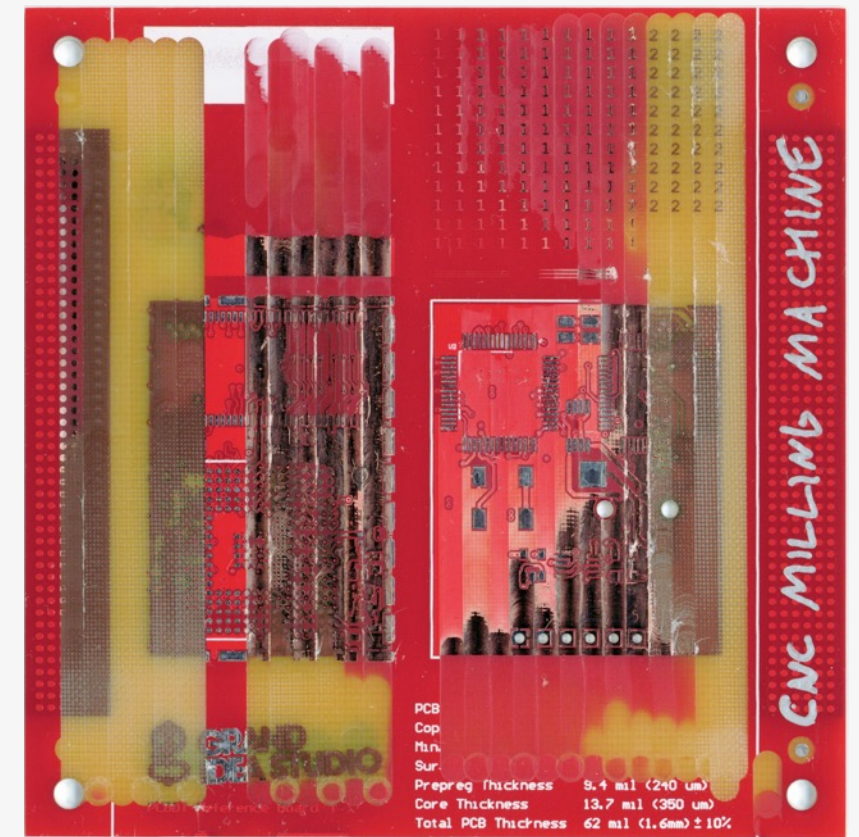
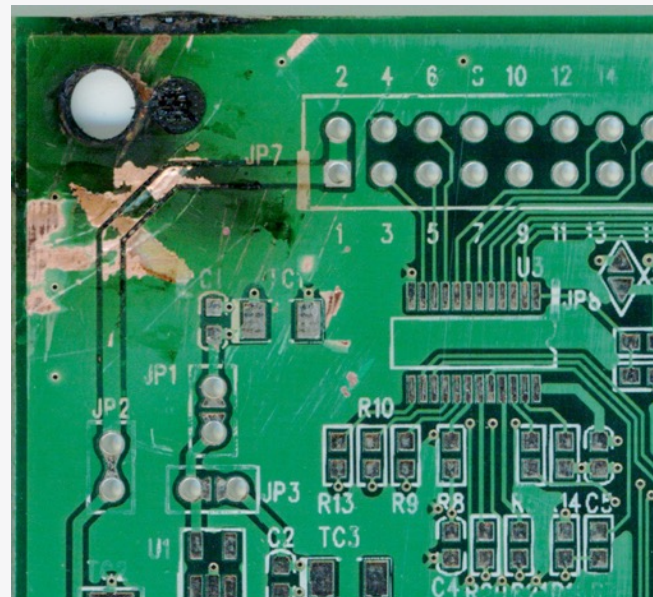
PCBDT Reference Board



iPhone 4 16GB Logic Board

Solder Mask Removal: Failures

- Hobby knife
- Electric/mechanical eraser
- Dremel tool
- CNC milling
- Chemical
 - Methylene chloride
 - Tetrahydrofuran
 - Acetone
- Heat
 - Heat gun
 - Butane torch



Delaying

- Sandpaper/rubbing stone
- Dremel tool
- CNC milling
- Surface grinding

Delaying: Sandpaper/Rubbing Stone

- Effective, lowest cost method
- Affix to work surface w/ double-sided tape
- Full strokes across the entire PCB @ hard pressure
 - One layer at a time
- Physical workout -> operator fatigue

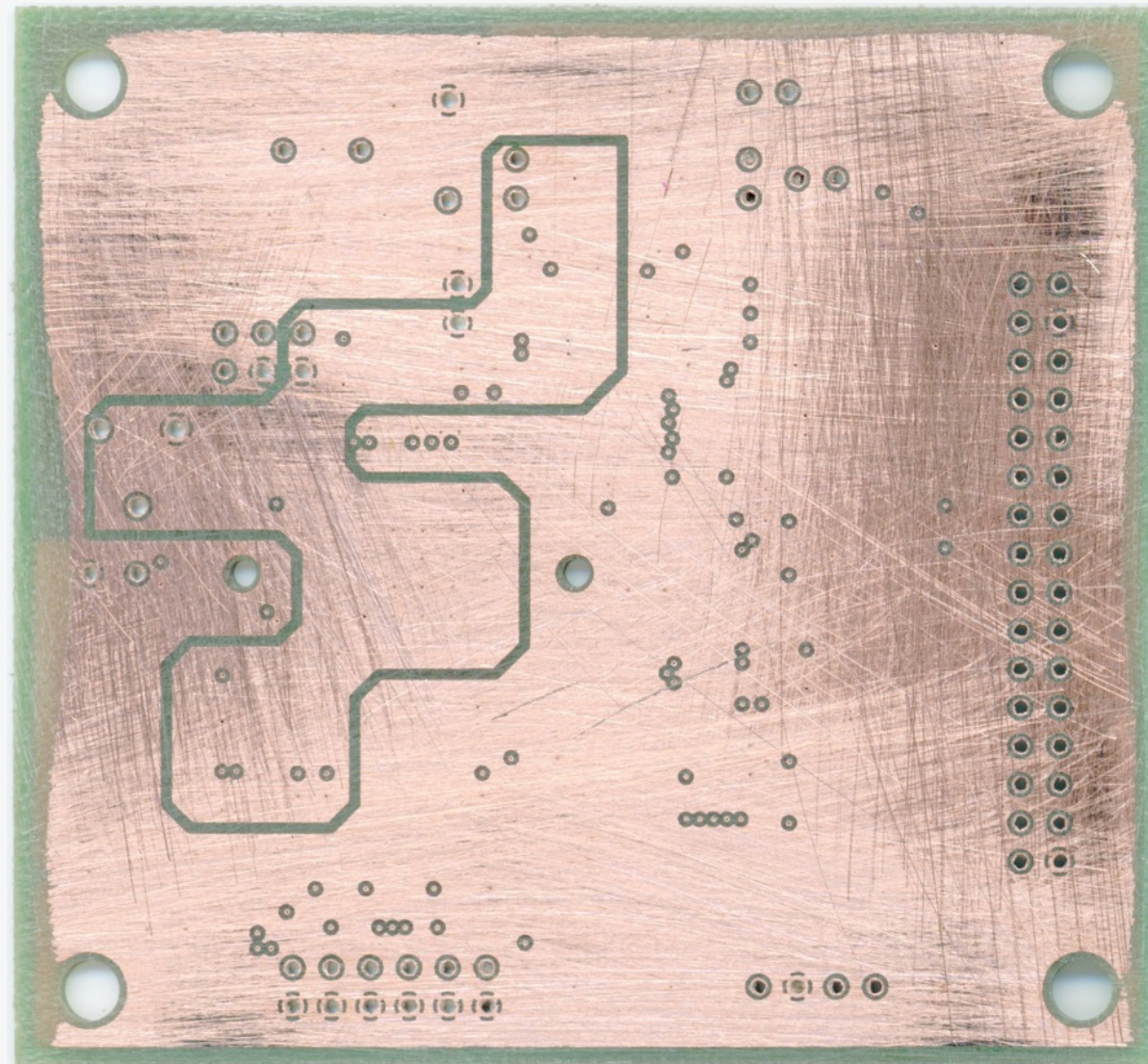


Delaying: Sandpaper/Rubbing Stone 2



Delaying: Sandpaper/Rubbing Stone 3

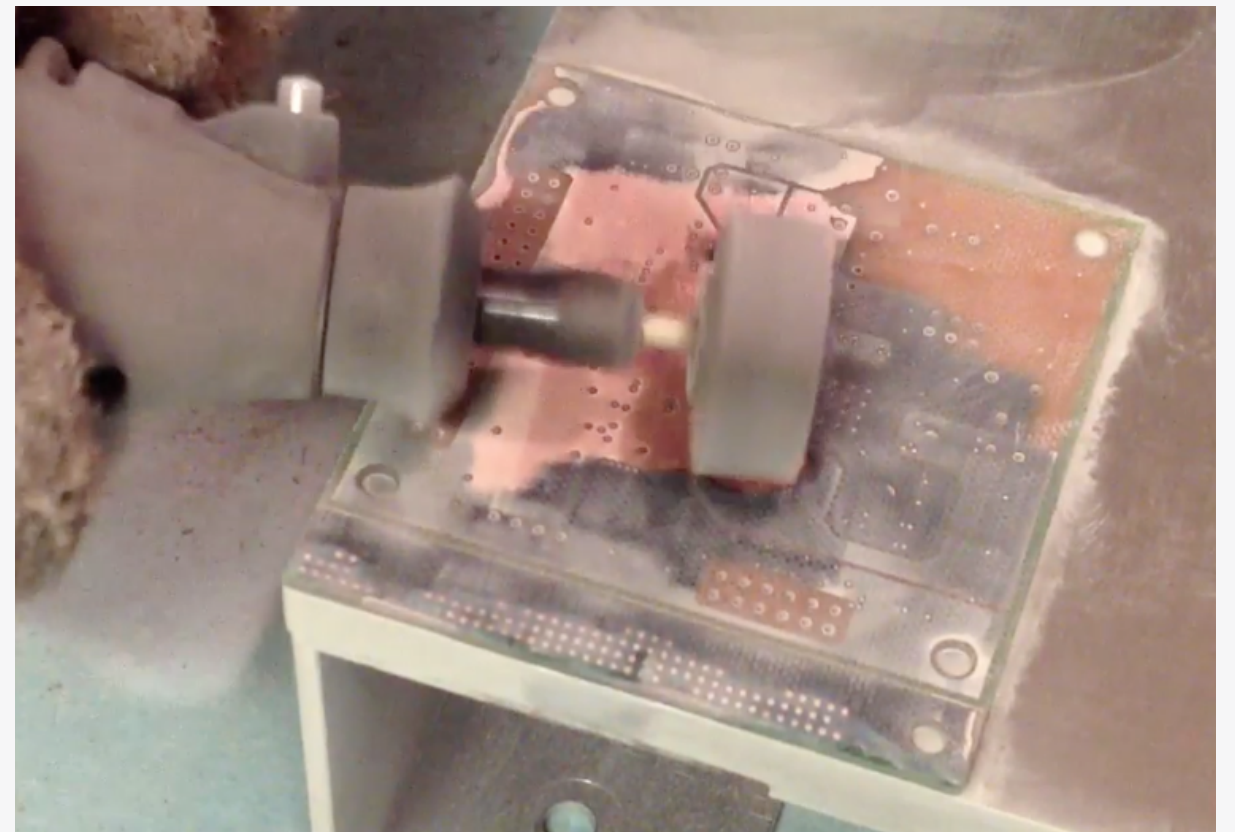
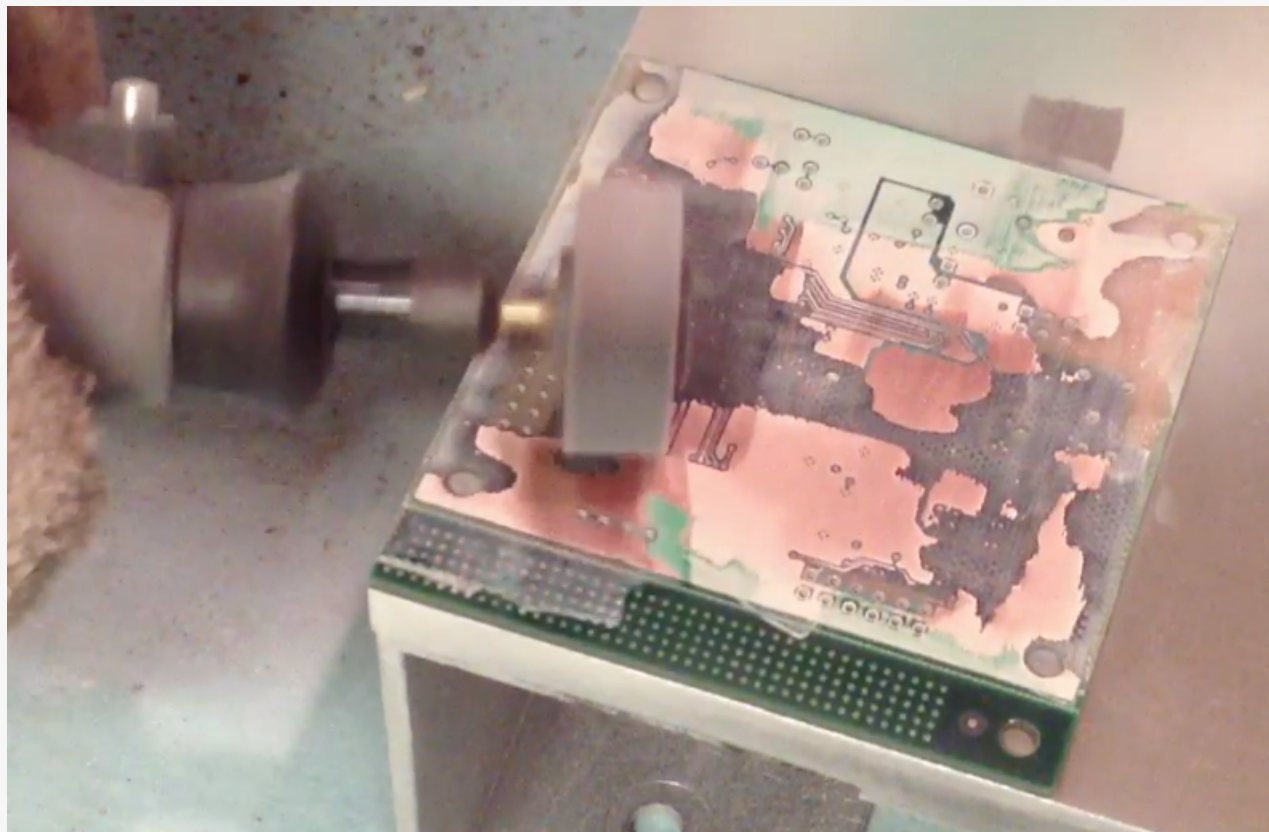
- Minor scratching of inner copper layer
- Noticeable wearing along edges due to uneven sanding



60/80 grit rubbing stone + 220 grit sandpaper

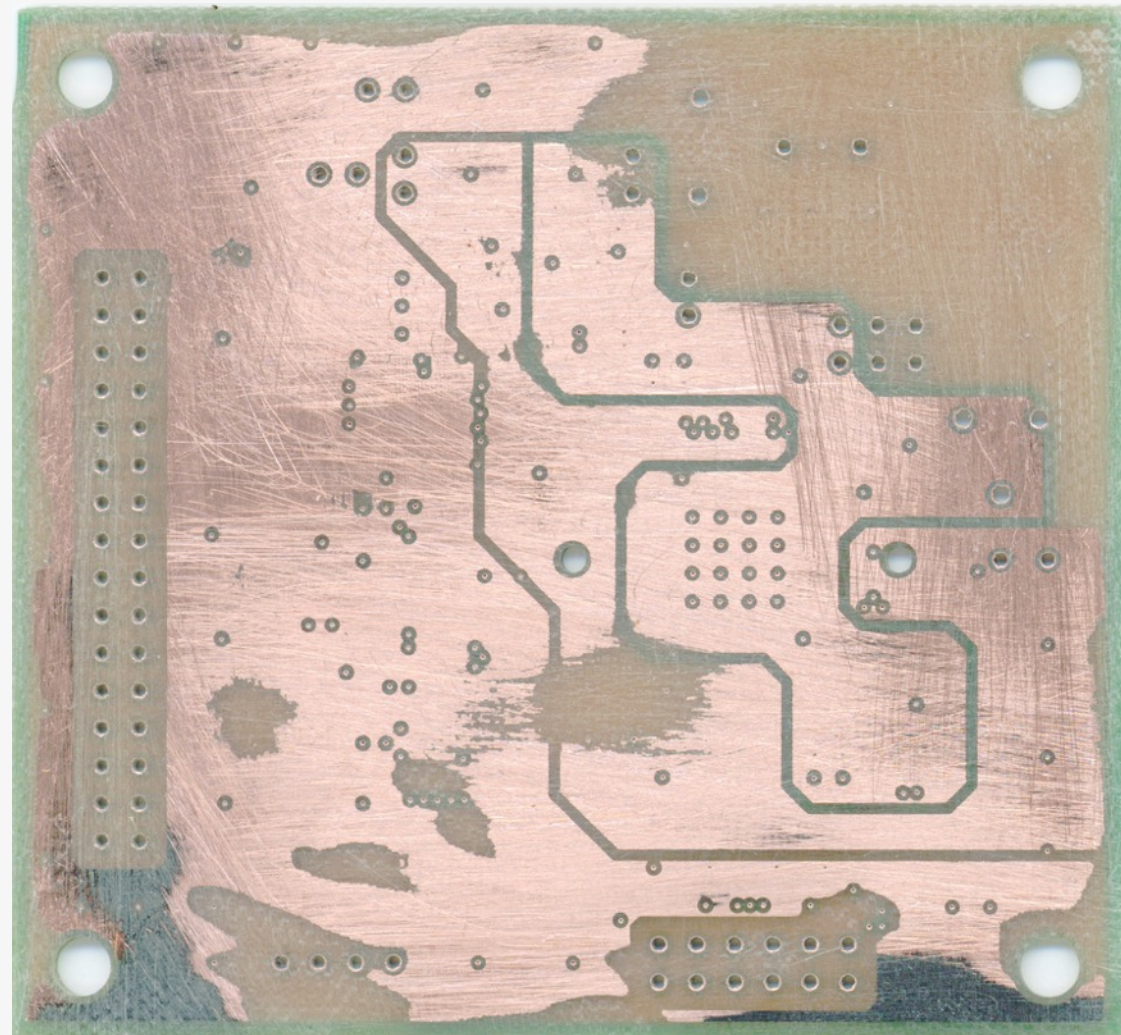
Delaying: Dremel Tool

- Off-the-shelf home improvement tool used for cutting, grinding, drilling, routing, polishing, & sanding
- Dremel MultiPro 395 w/ 503 Flapwheel (120 grit, 3/8" wide)
- Back and forth across the PCB @ medium pressure



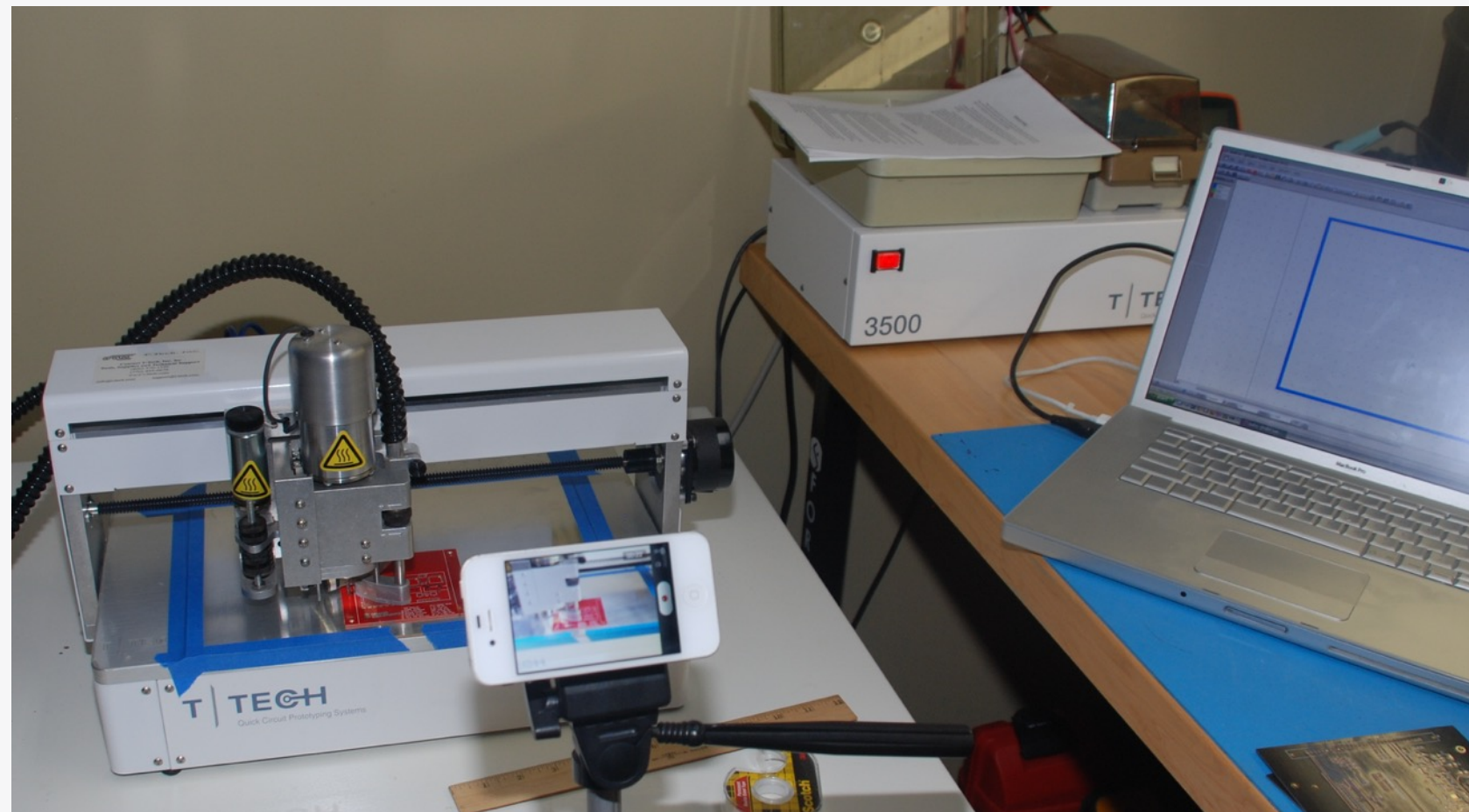
Delaying: Dremel Tool 2

- Difficult to keep tool flat against the PCB
 - Dremel 225 flexible shaft will help move the tool's body away from the work surface
- Easy to accidentally remove too much material from the target surface
 - More care/practice required!



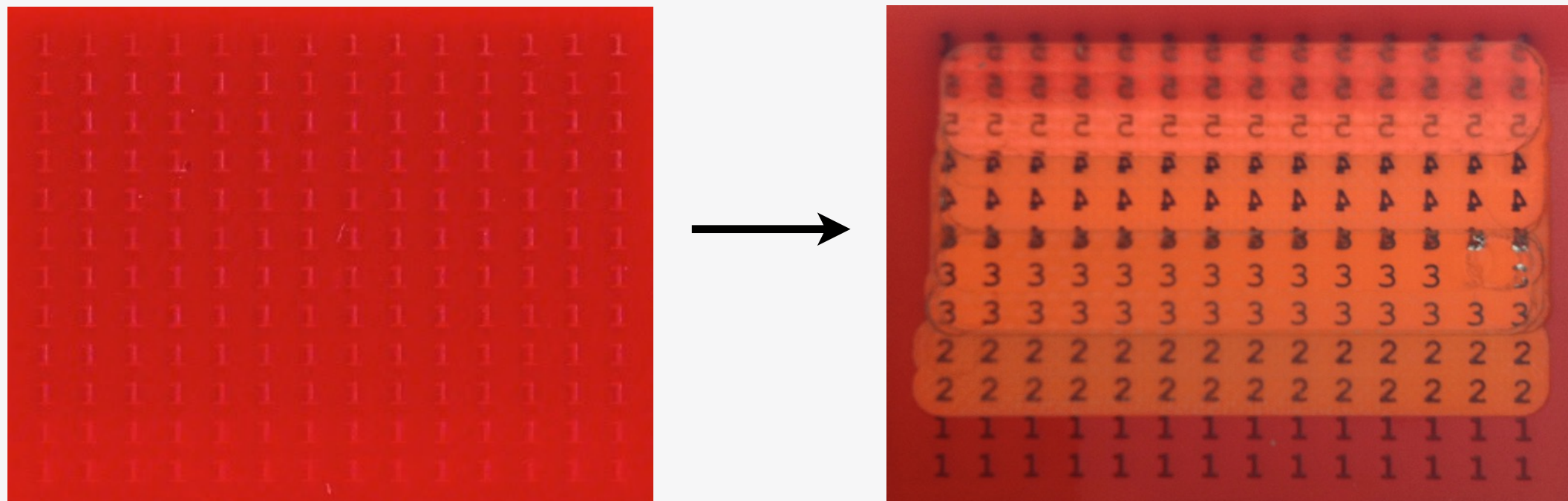
Delaying: CNC Milling

- T-Tech QuickCircuit 5000 PCB Prototyping System
 - Z-axis can be manually adjusted in 10um (0.4mil) increments
- Think & Tinker MN208-1250-019F 1/8" diameter carbide endmill
- IsoPro 2.7 for control and manipulation of milling, drilling, and routing procedures



Delaying: CNC Milling 2

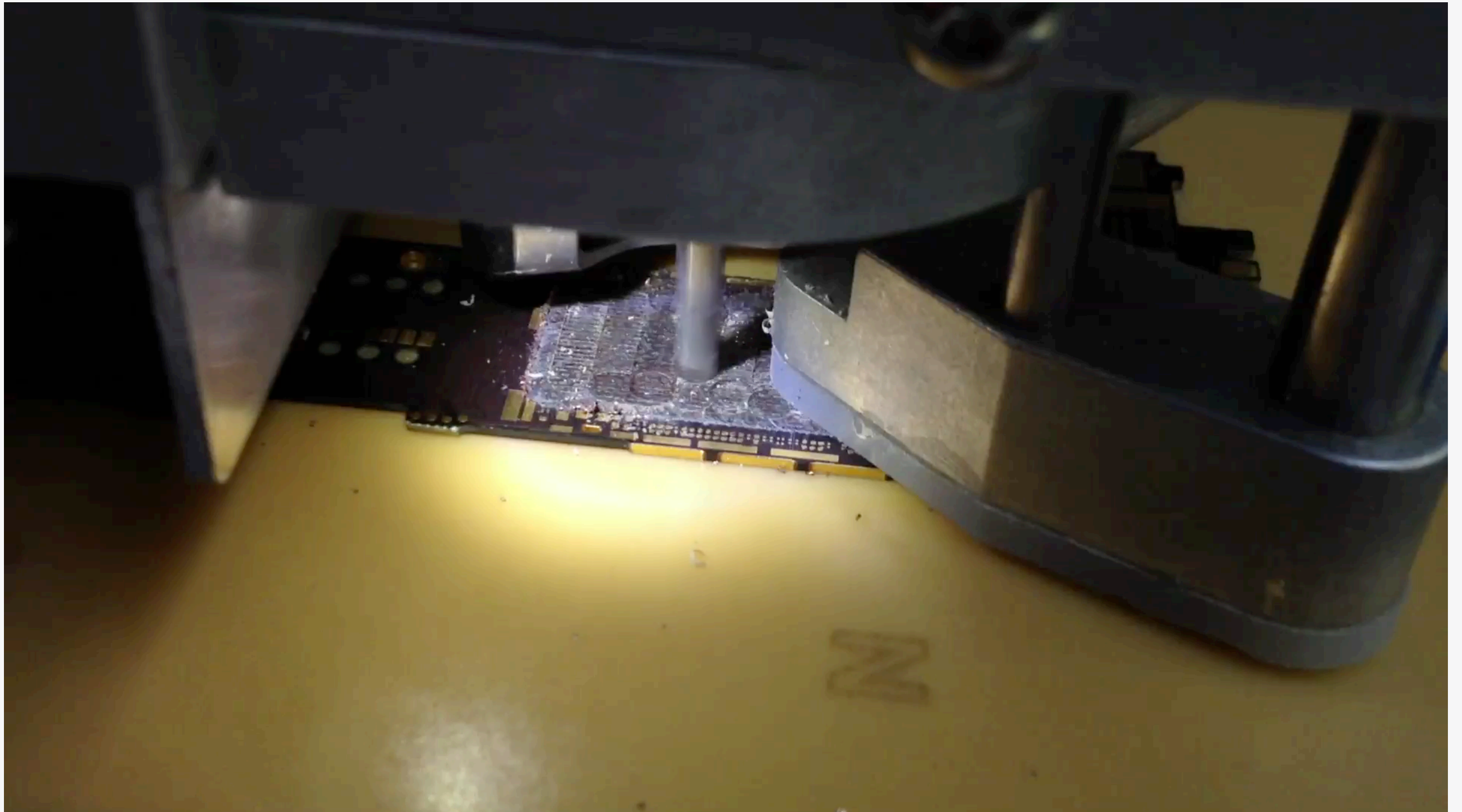
- PCBDT Reference Board
- Z-axis depth incrementally adjusted
- Manual jog to mill away the desired area(s)
- Resulting PCB has a stair-step that can be visually identified and felt with a finger
 - Proved that it was possible to access a specific copper layer using CNC



Delaying: CNC Milling 3

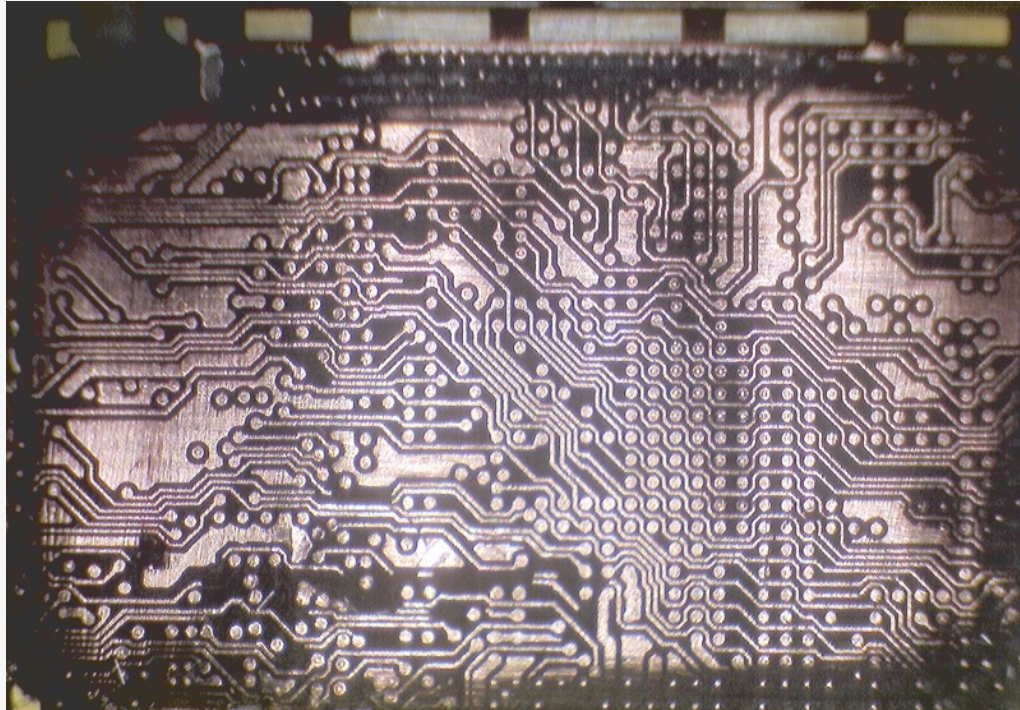
- iPhone 4 16GB Logic Board
- Mechanical outline of the desired PCB area created in IsoPro
- Configured to rout out all material internal to that area
 - Allows for accurate, repeatable, and automatic positioning of the milling path
- Z-axis depth adjusted in 1mil increments
- When layer of copper was visible beneath the substrate, switched to manual abrasion using fiberglass scratch brush
- Repeat

Delaying: CNC Milling 4

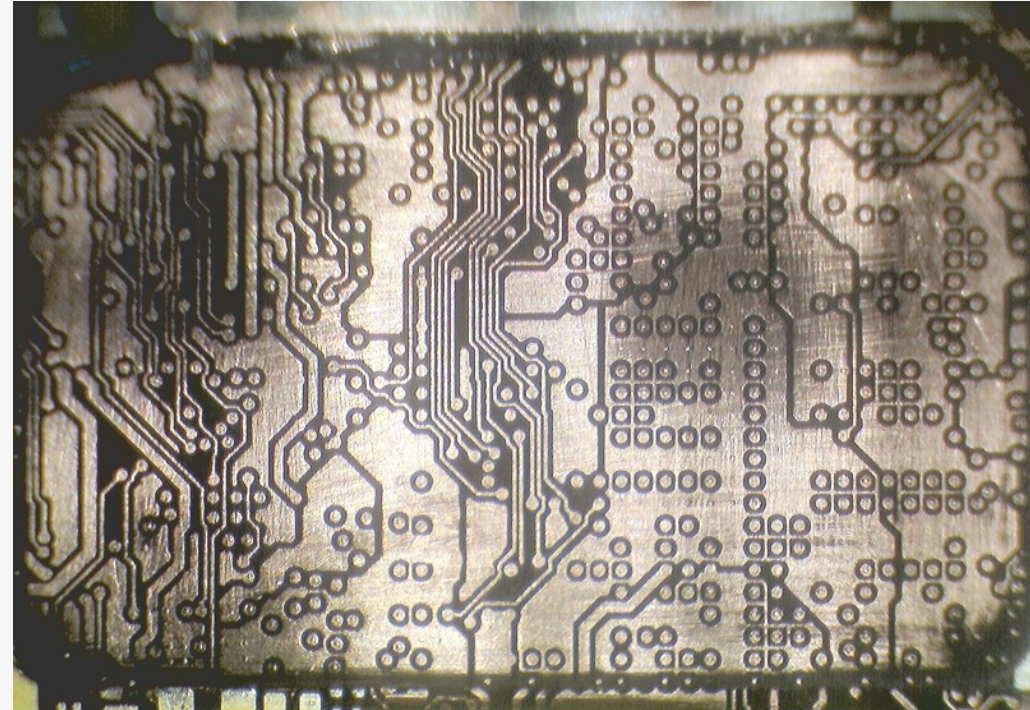


Delaying: CNC Milling 5

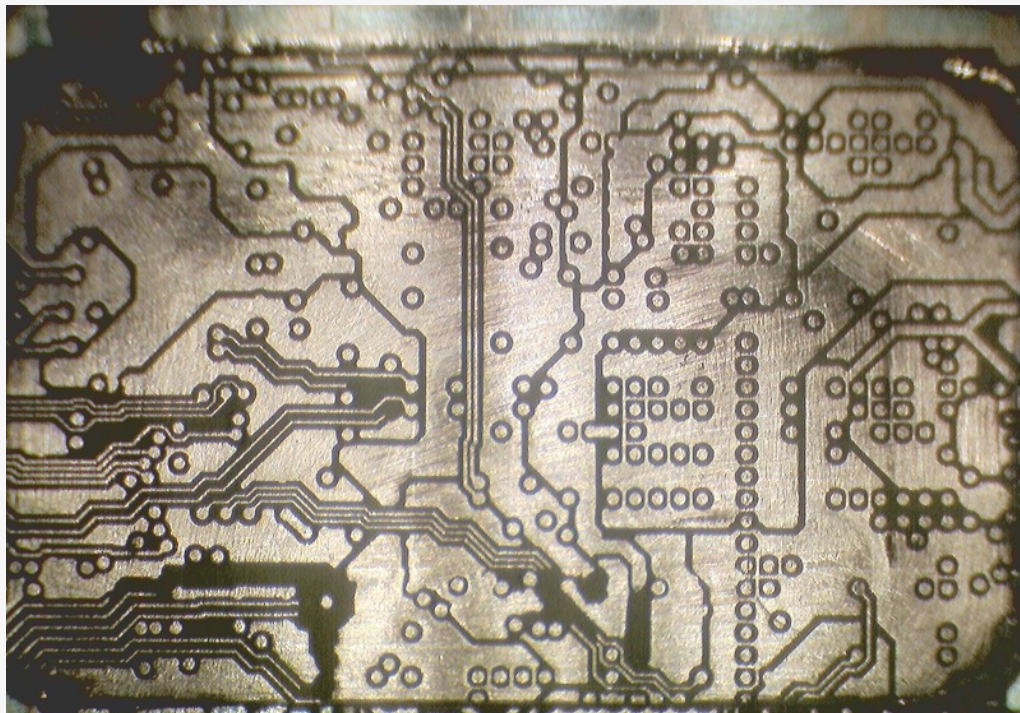
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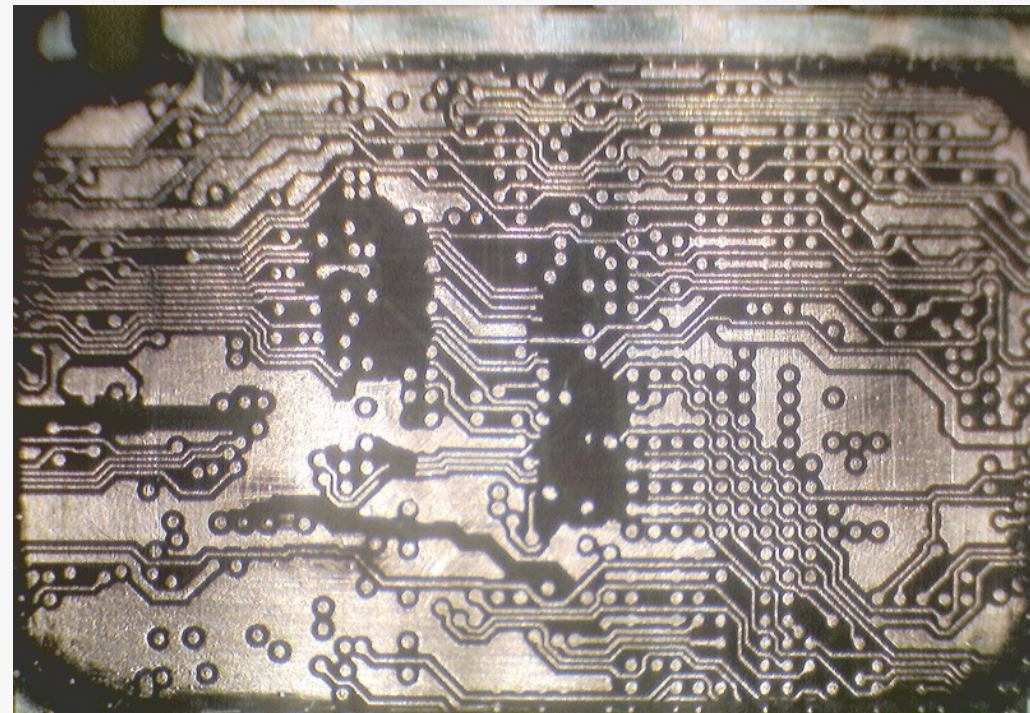
3



4



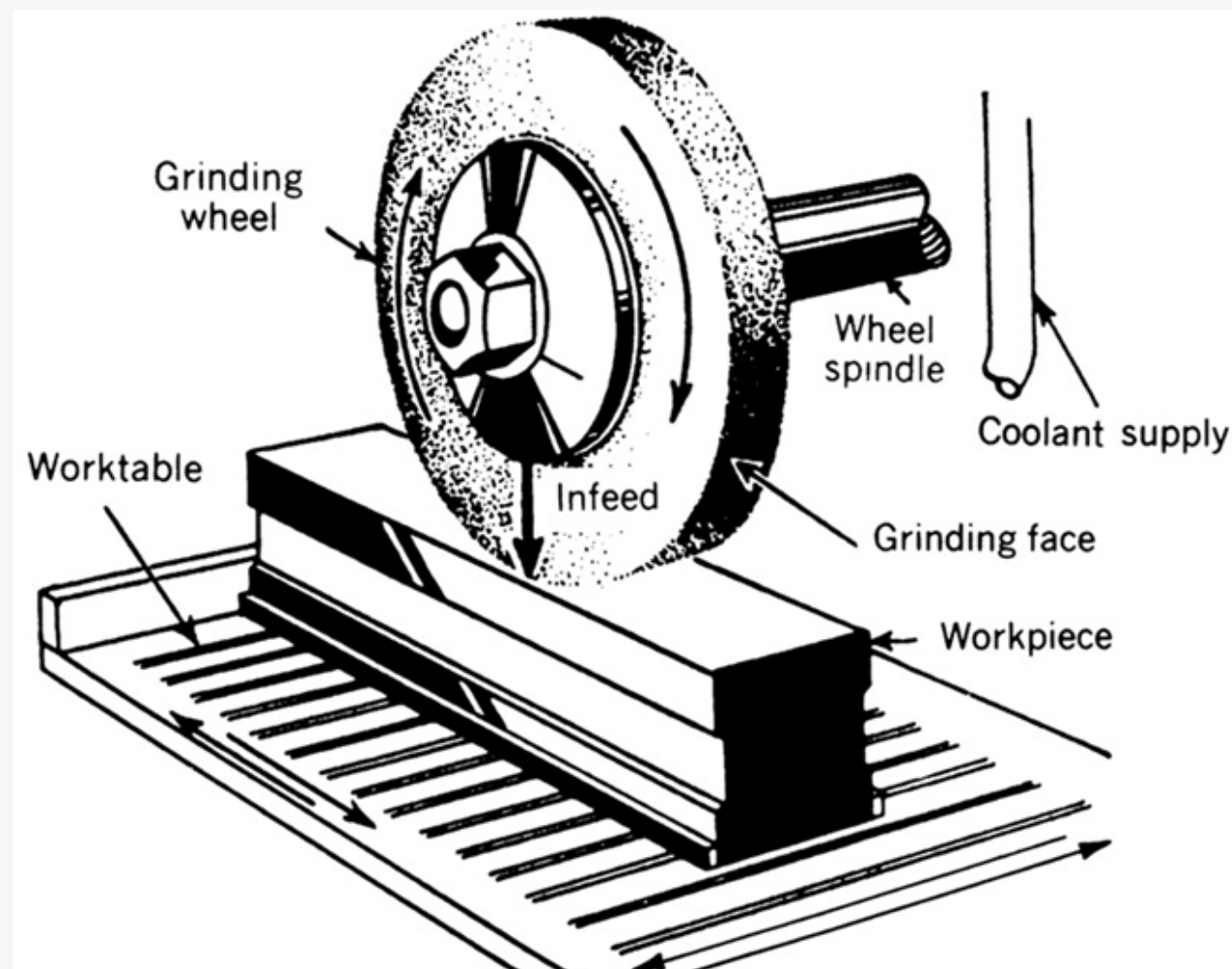
5



iPhone 4 16GB Logic Board (0.92" x 0.58" area)

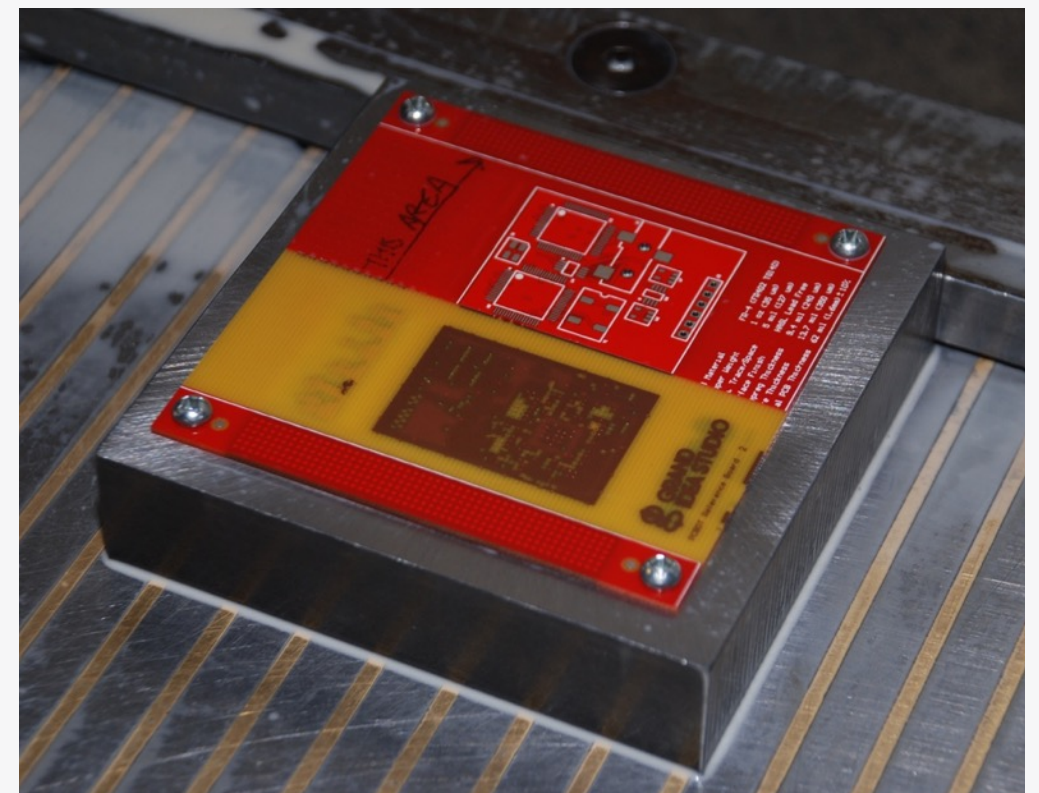
Delaying: Surface Grinding

- Typically used for material grinding & surface finishing
- Consists of a rotating abrasive wheel (grinding wheel), work surface, and reciprocating or rotary table (manual or computer control)



Delaying: Surface Grinding 2

- Blohm PROFIMAT CNC Creep Feed Surface Grinder w/ Siemens SINUMERIK 810G controller & Radiac 1 3/8"-wide wheel @ General Grinding, Oakland, CA
 - Depth control in 0.1mil increments
- Target PCB mounted to steel block (held in place by magnetic chuck)

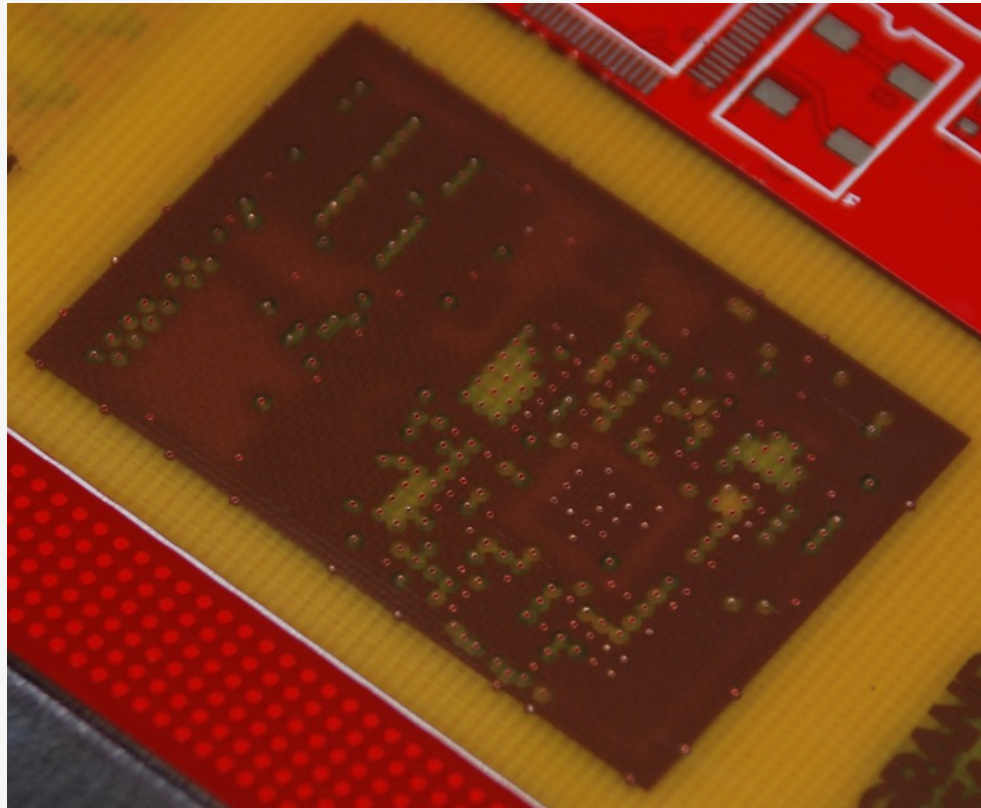


Delaying: Surface Grinding 3

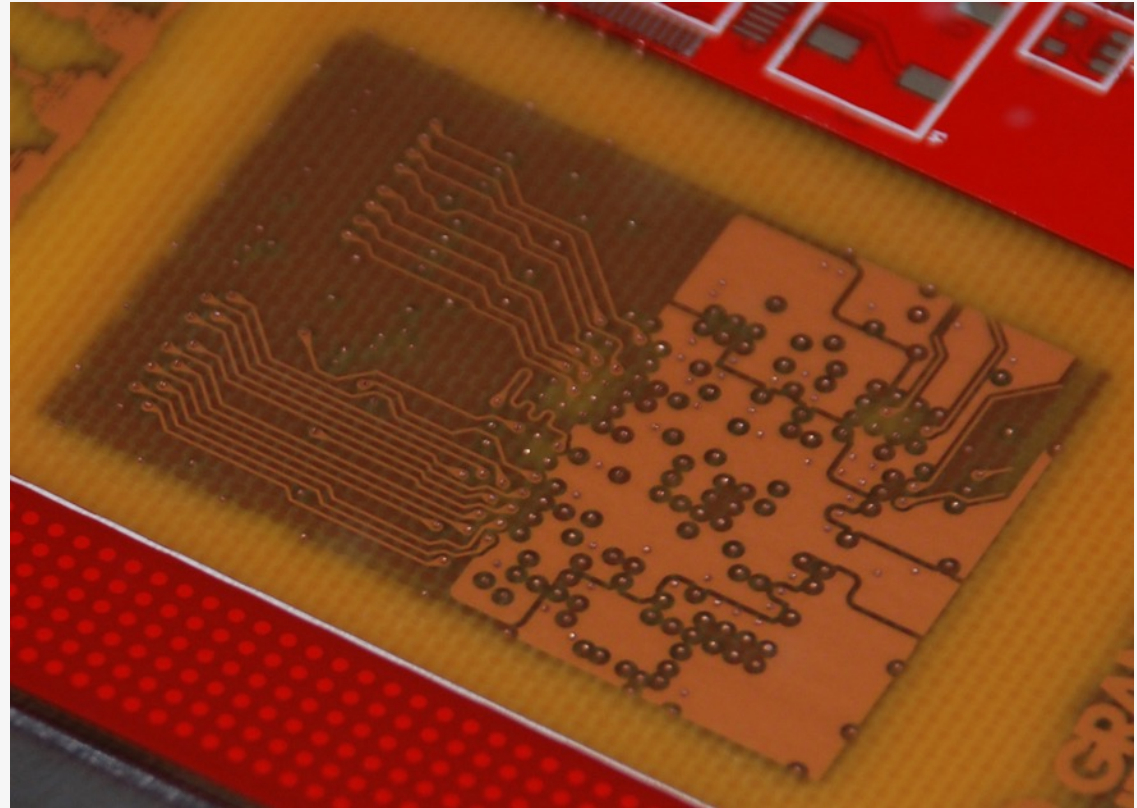


Delaying: Surface Grinding 4

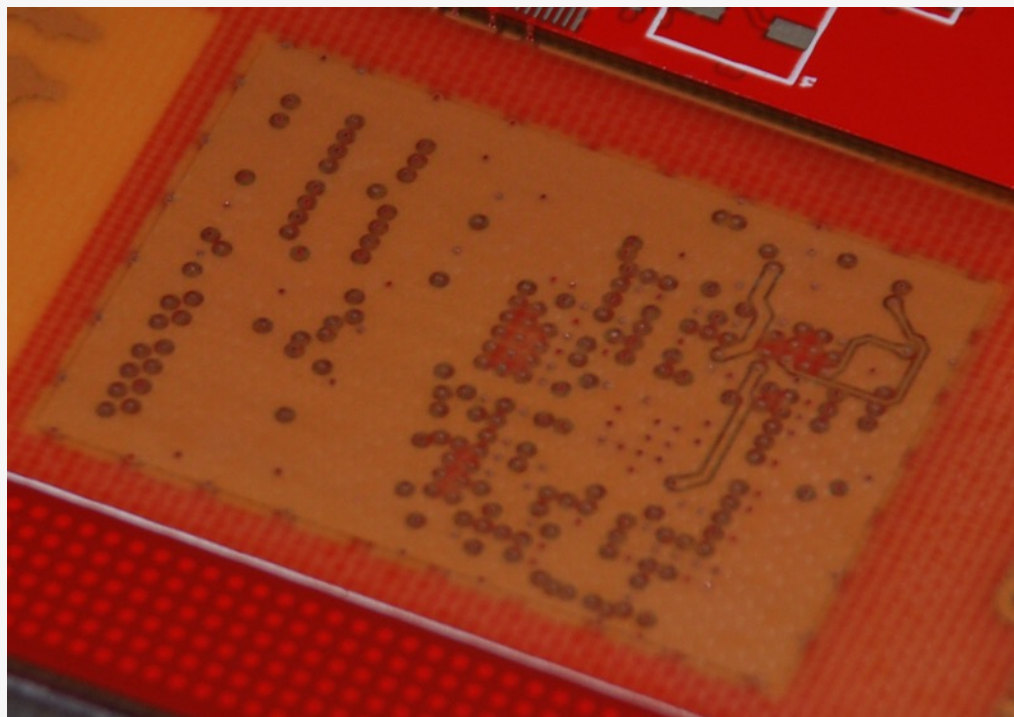
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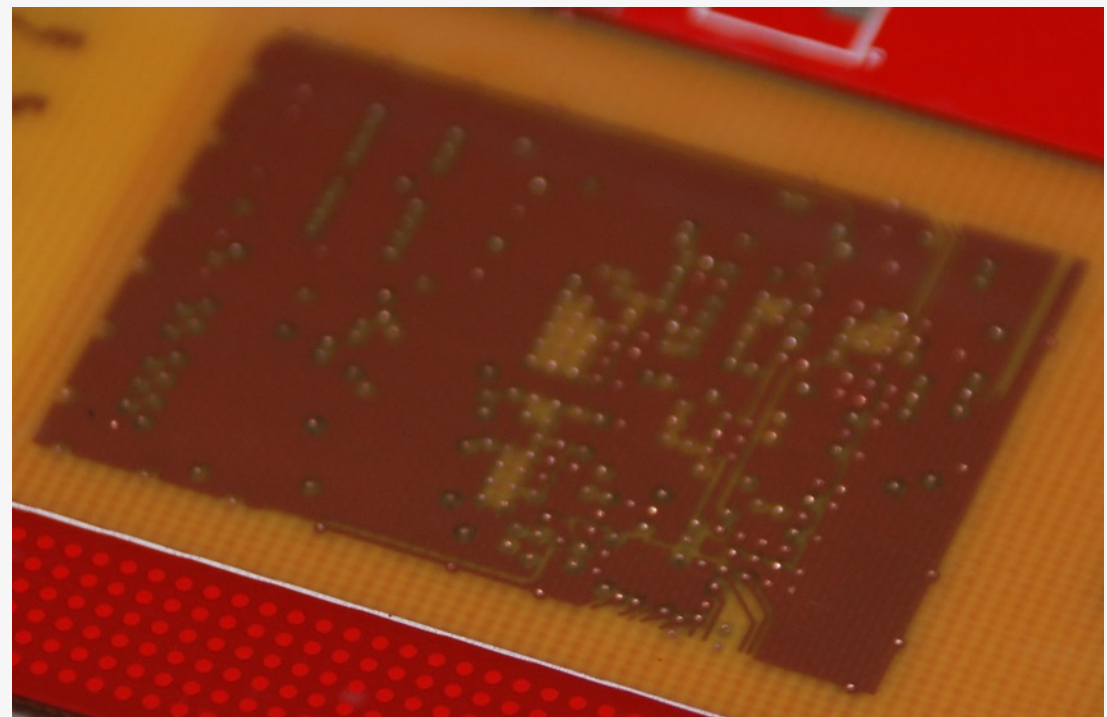
3



4

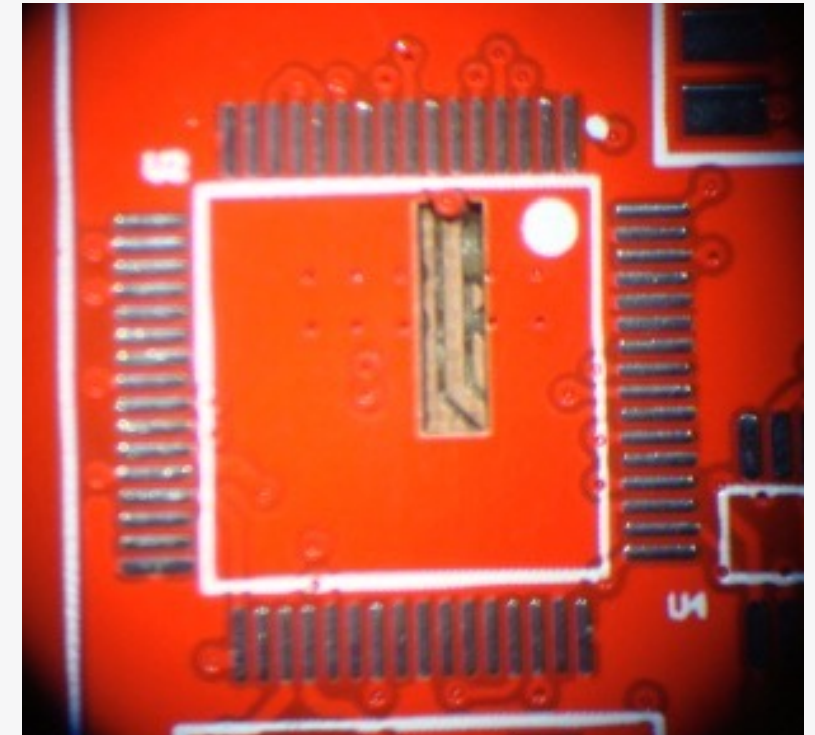
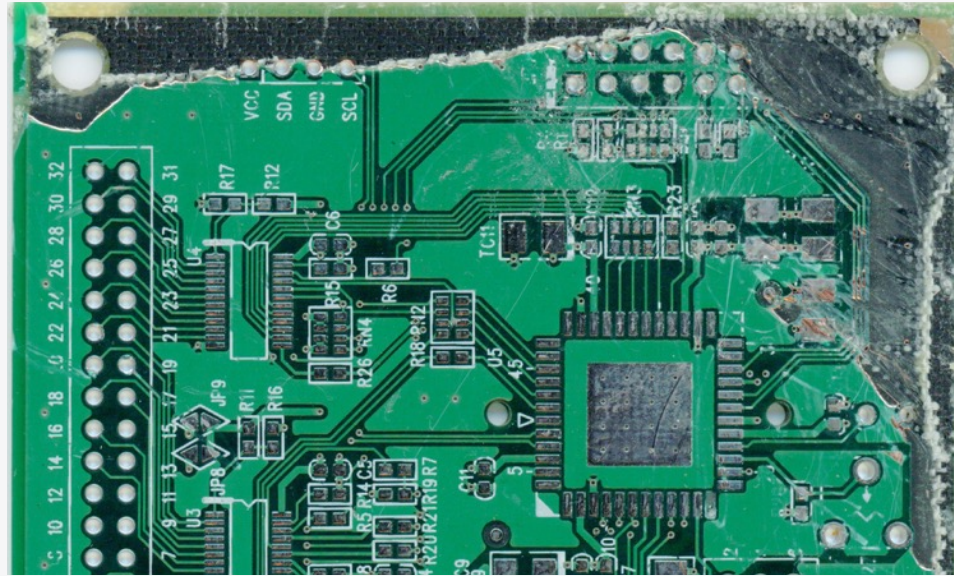


5



Delaying: Failures

- Heat
 - Heat gun
 - Hot knife
- Laser
 - UV/CO2

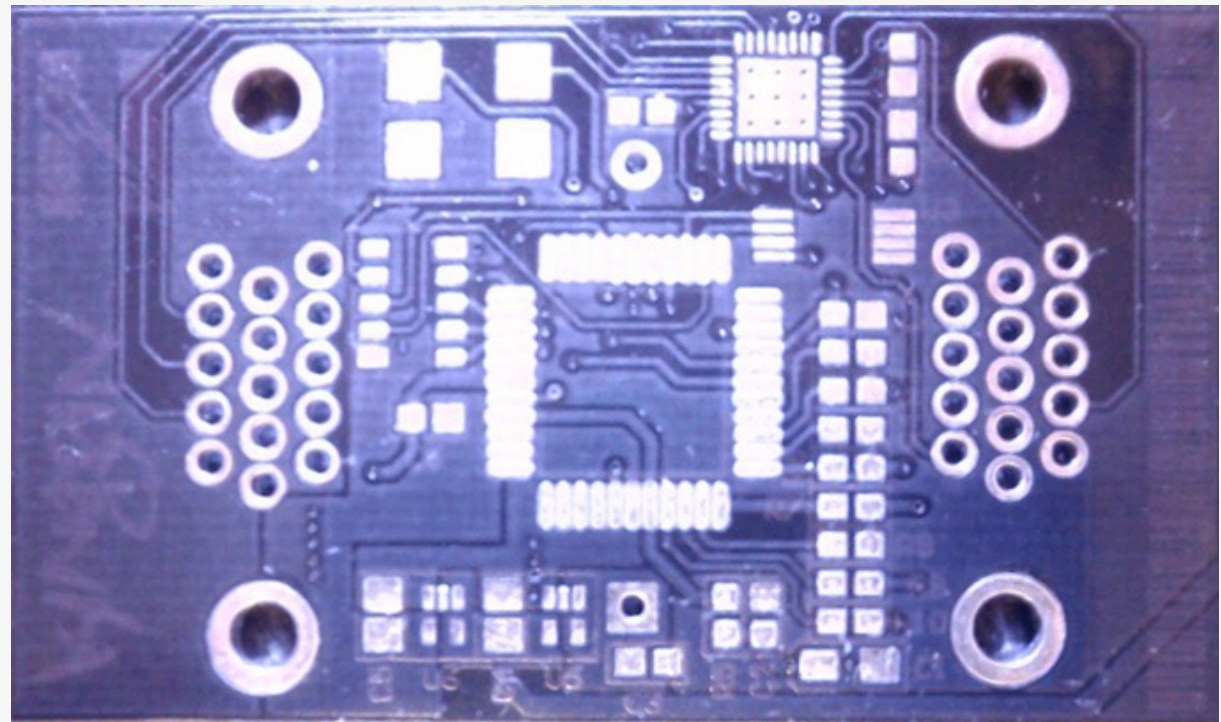


Imaging

- Infrared (IR)
- X-ray (2D)
- Computerized Tomography (3D)

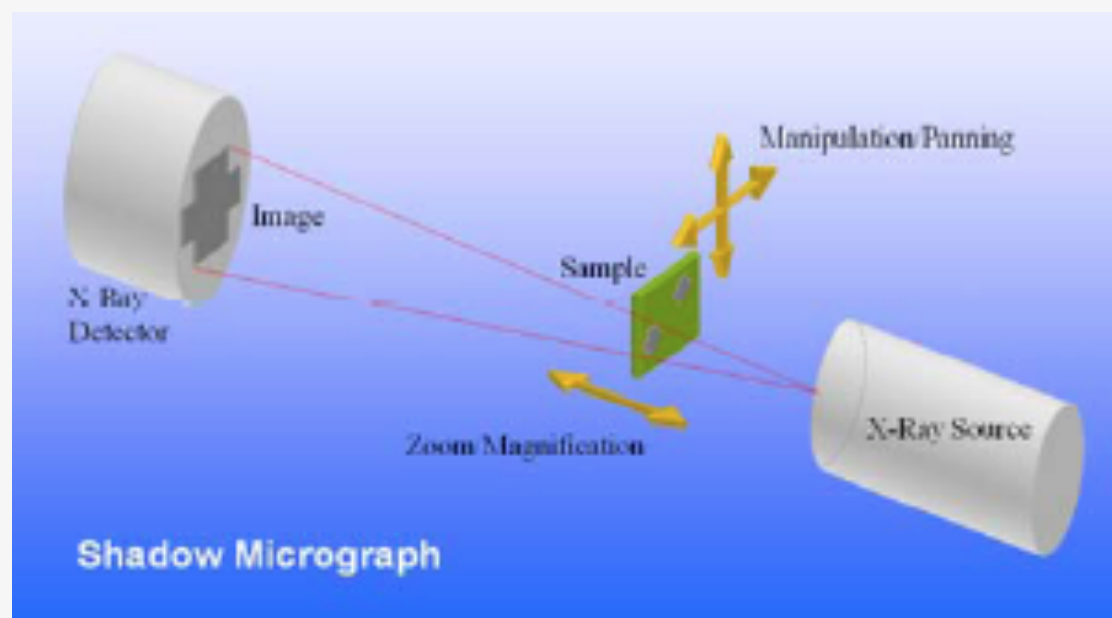
Imaging: Infrared (IR)

- Many types of solder mask coatings will appear transparent when illuminated with IR
- Logitech C920 webcam w/ removed IR block filter + Sony TV remote control
- Image quality can be enhanced with wider beam of IR light



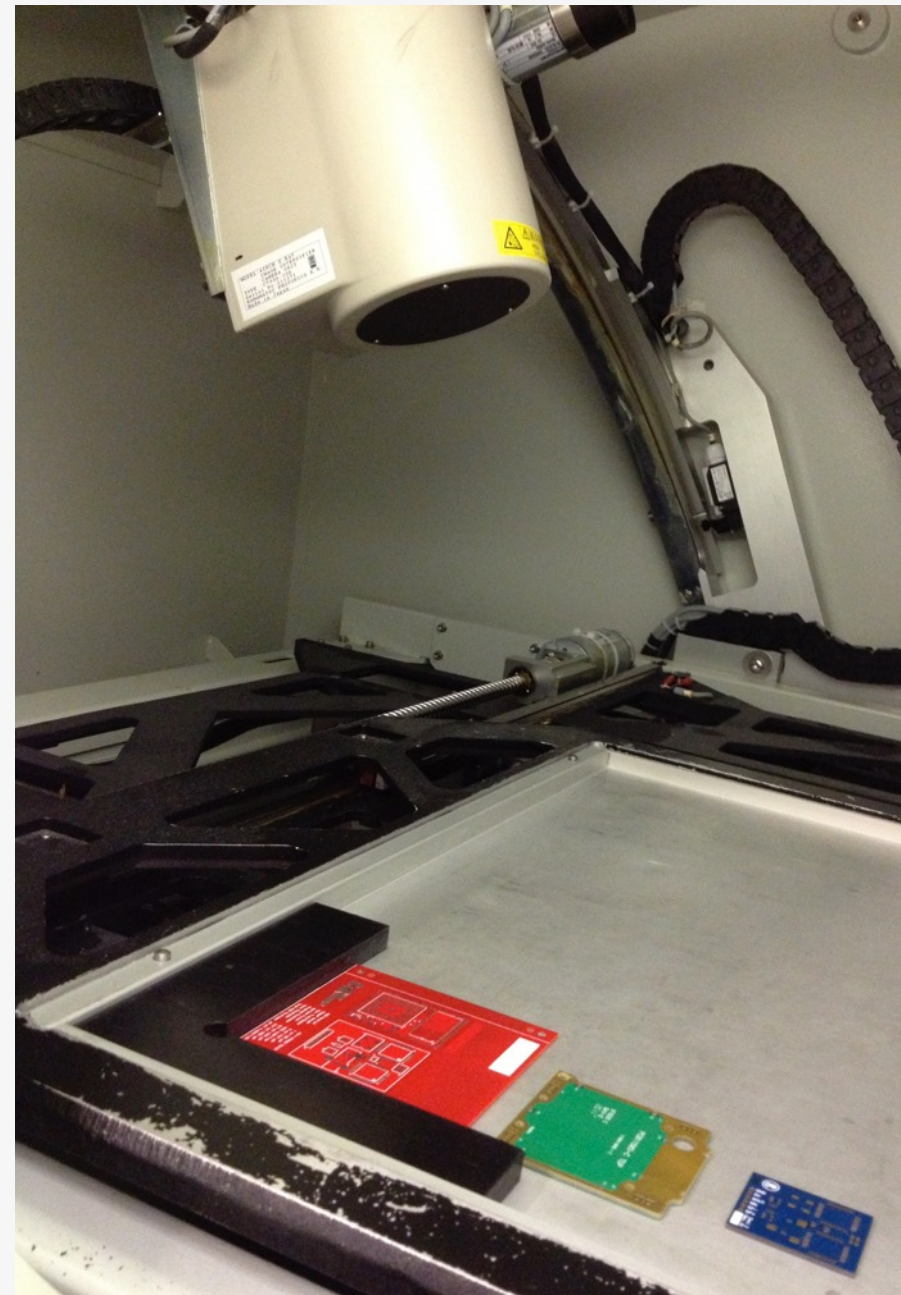
Imaging: X-Ray (2D)

- Typically used during PCB assembly (component placement/solder quality) or failure analysis (troubleshooting defective features)
- X-rays passed through target and received on detector
 - All materials absorb radiation differently depending on density, atomic number, and thickness
- Provides a composite image of all layers in target



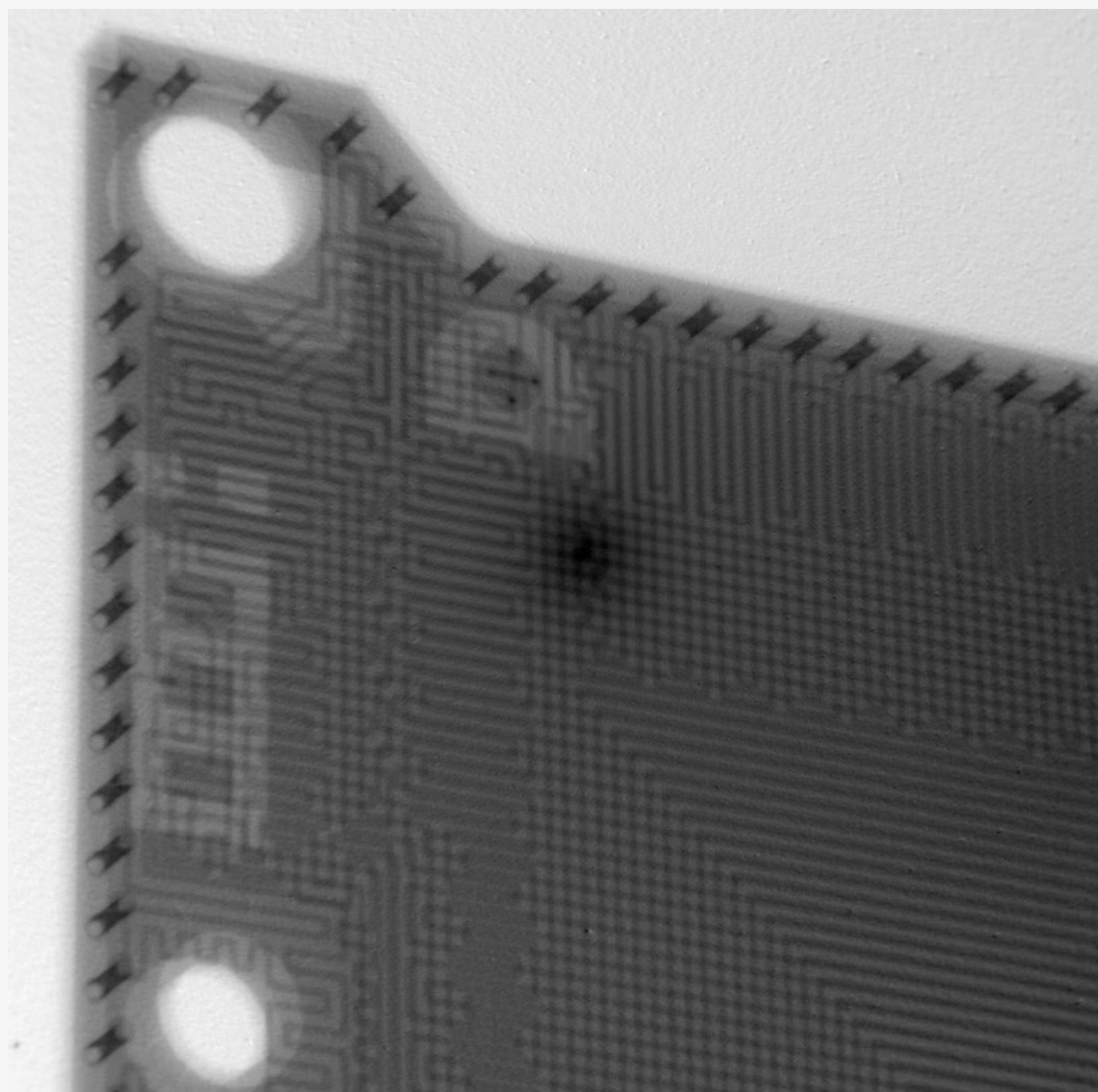
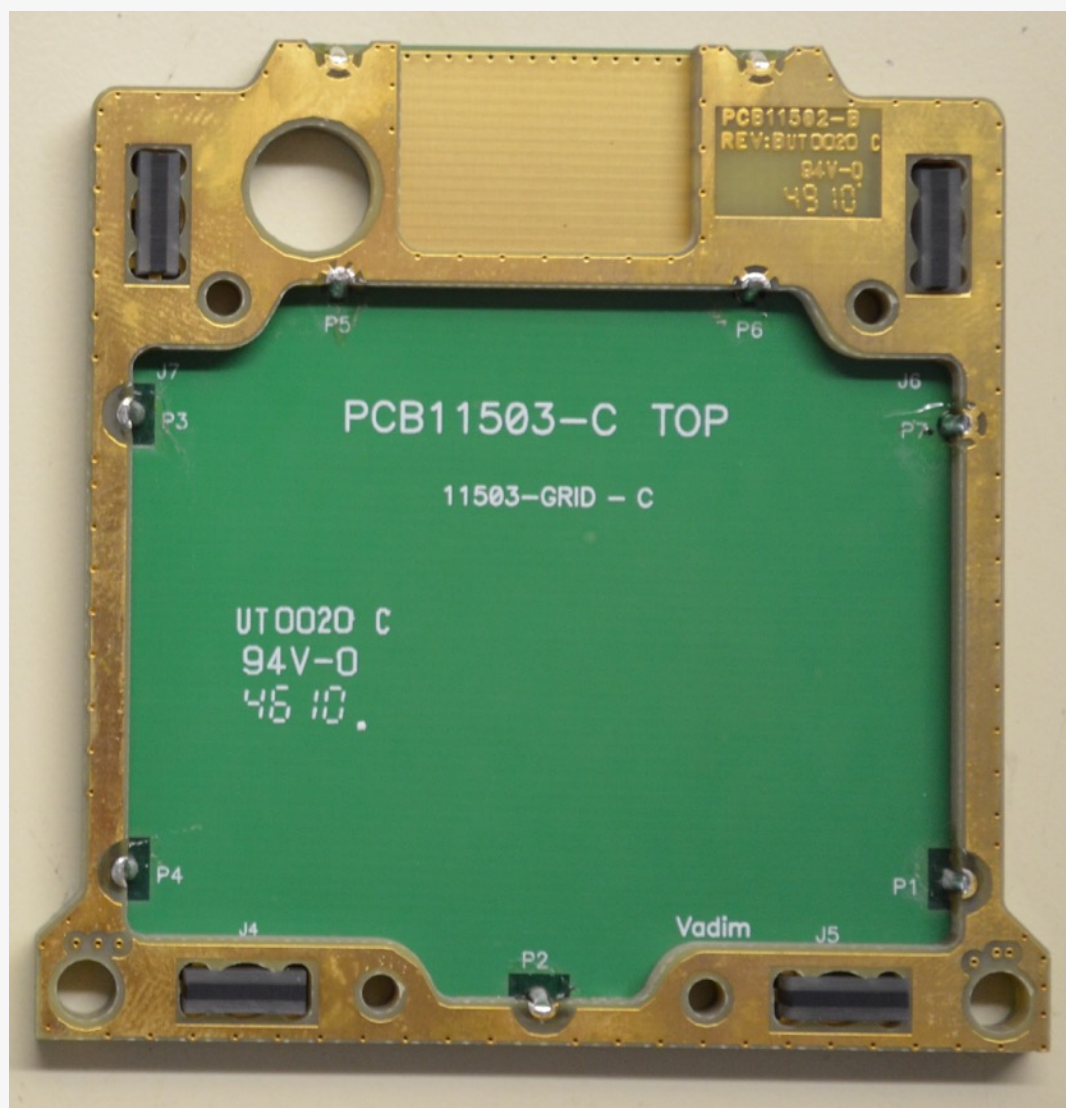
Imaging: X-Ray (2D) 2

- Nordson DAGE XD7500VR X-ray Inspection System @ Sonic Manufacturing, Fremont, CA



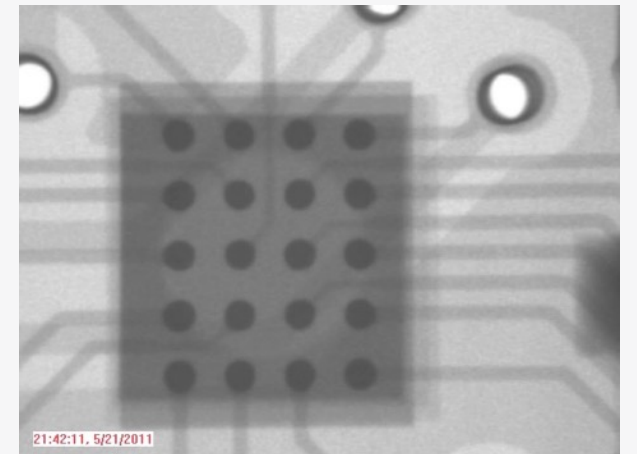
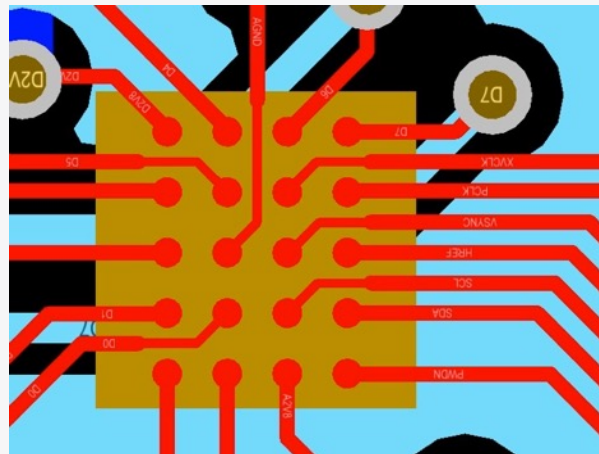
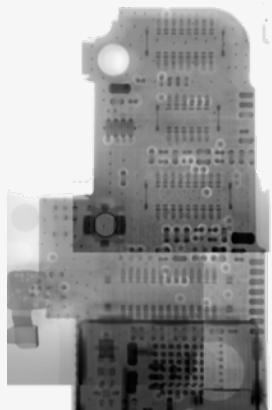
Imaging: X-Ray (2D) 3

- Can get clues about PCB construction/layout, component location, layer count, hidden/embedded features
- VeriFone PINpad 1000SE active security envelope

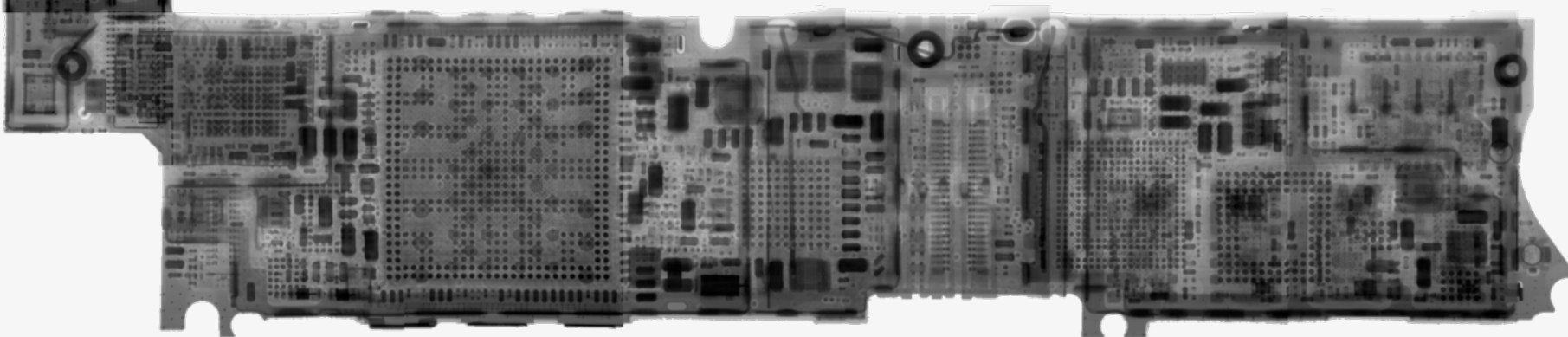


Imaging: X-Ray (2D) 4

- For simple boards, can visually follow traces/interconnections
 - Composite image makes it difficult to determine on which layer a particular trace is located
 - Manipulating the X-ray angle and field-of-view in real time will help

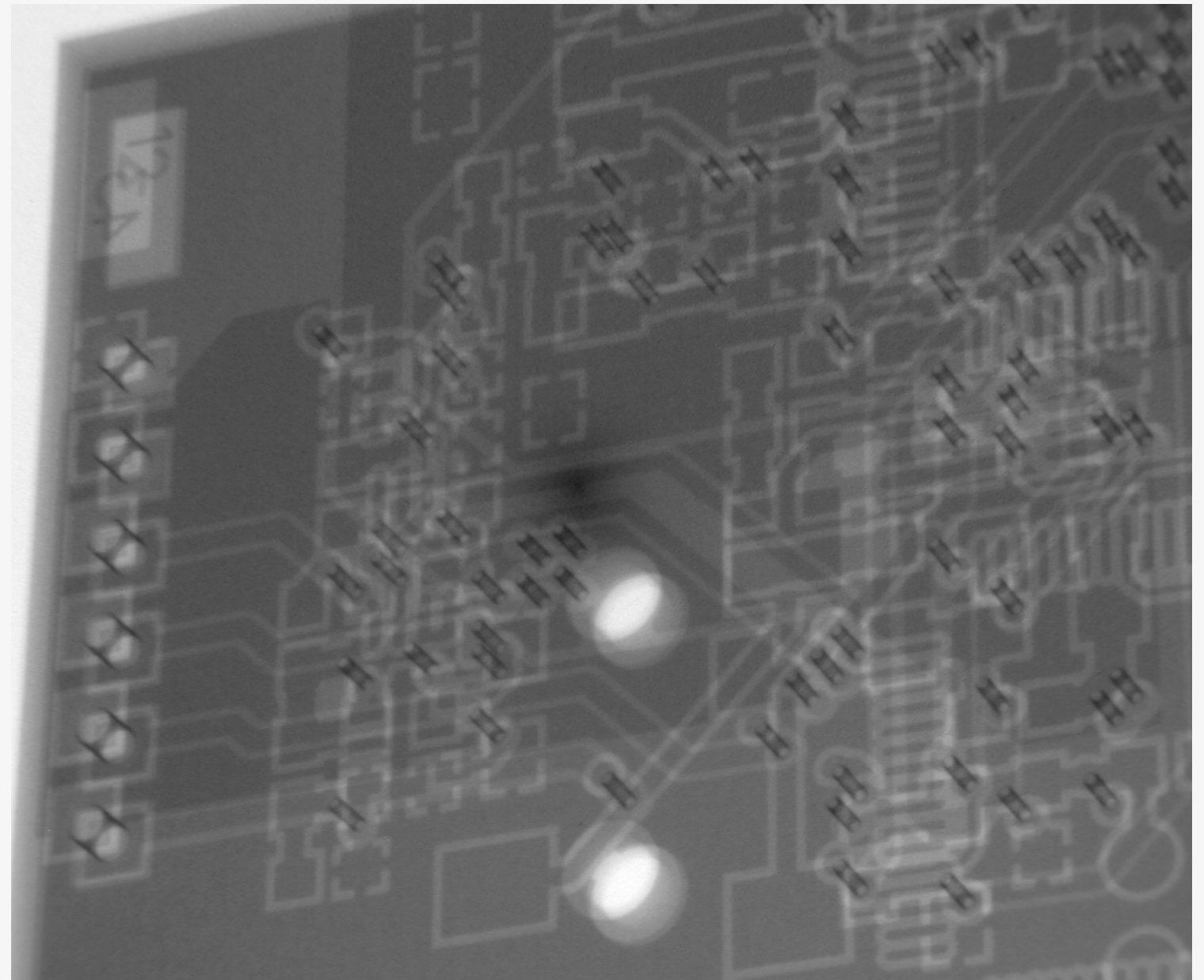
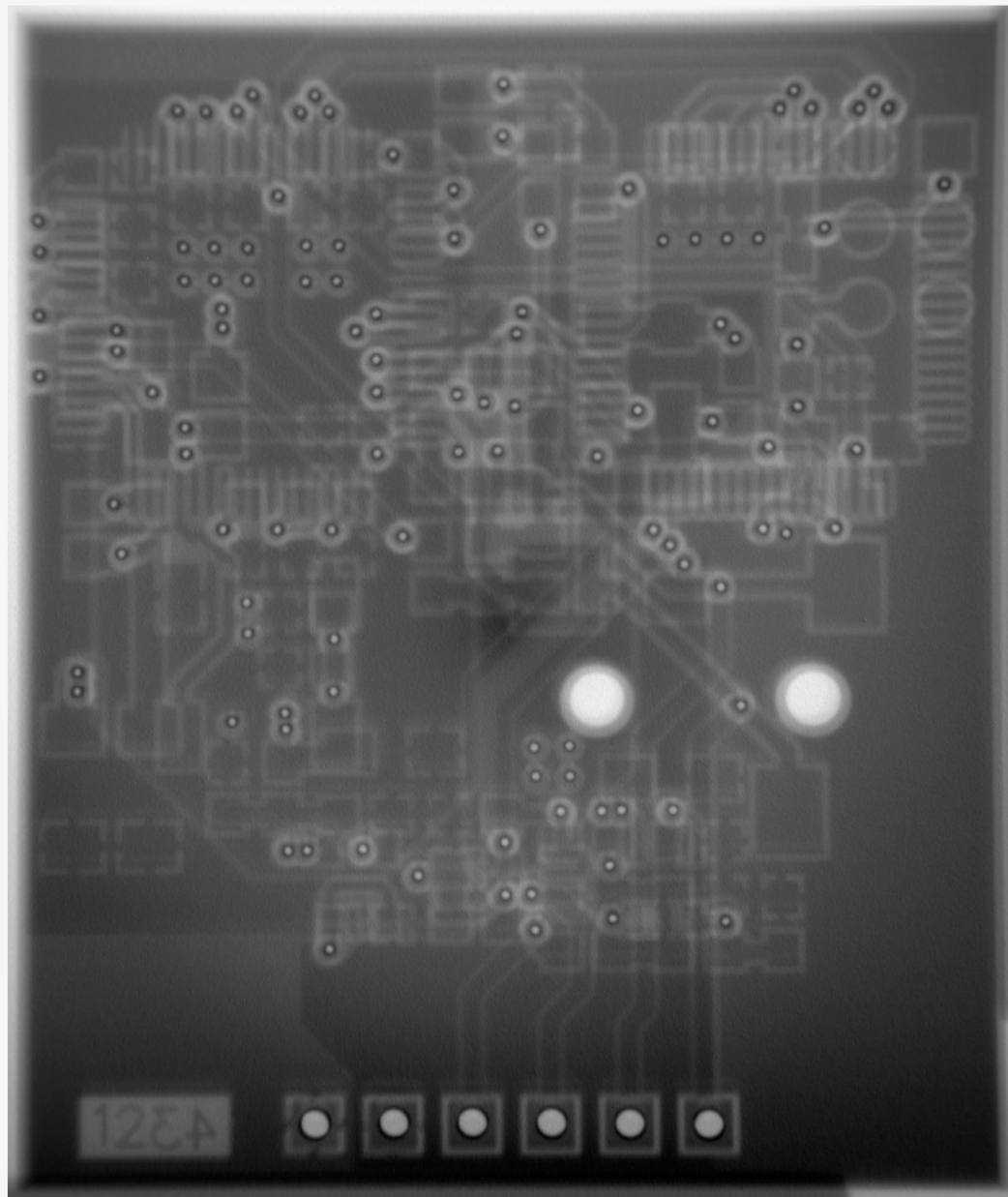


20-pin uBGA (CSP3)



iPhone 4 16GB Assembled

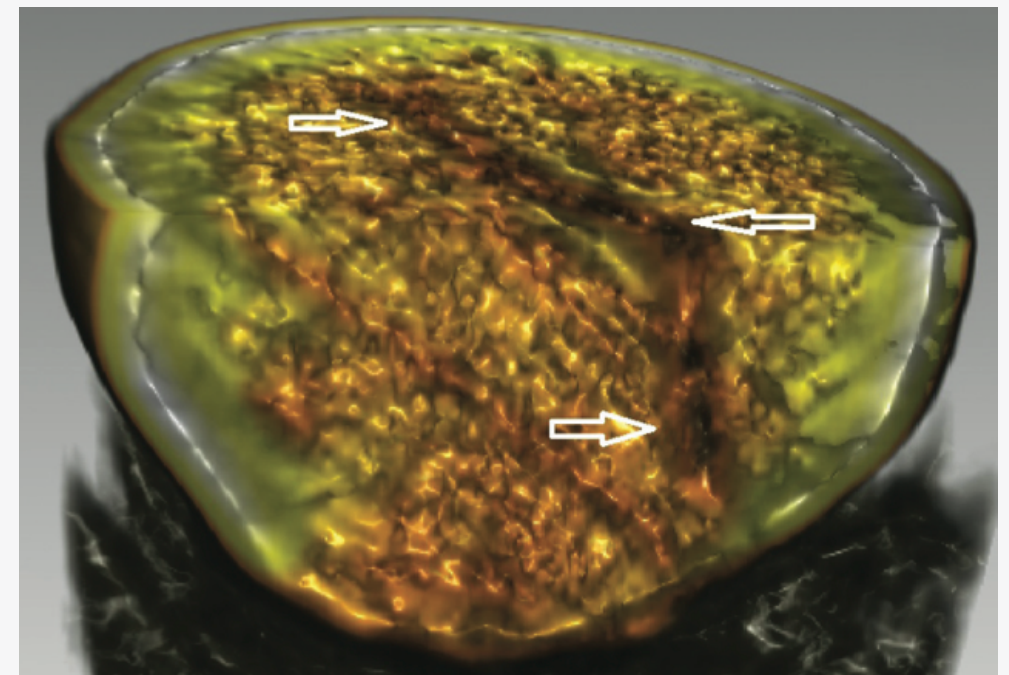
Imaging: X-Ray (2D) 5



Emic 2 Text-to-Speech Module

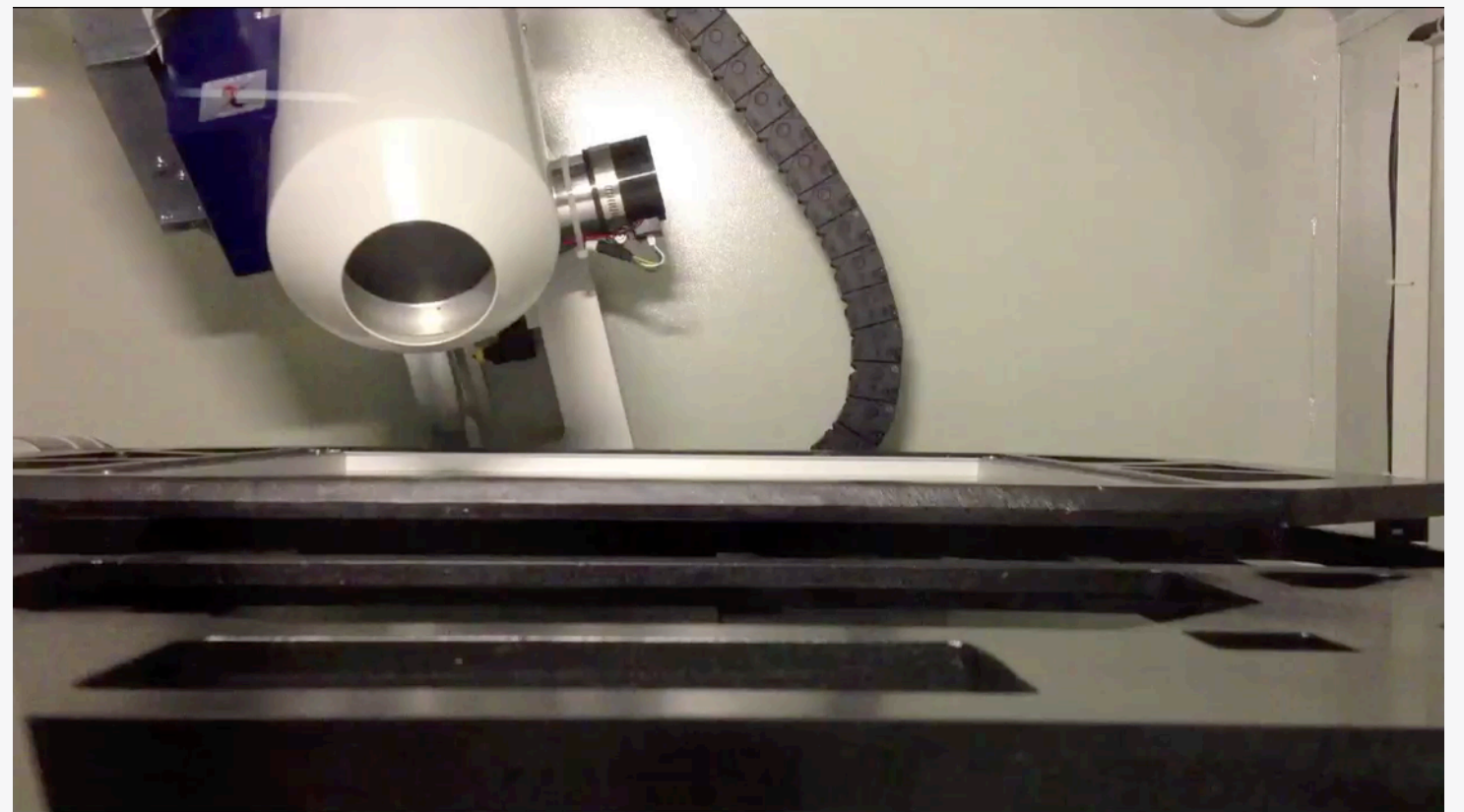
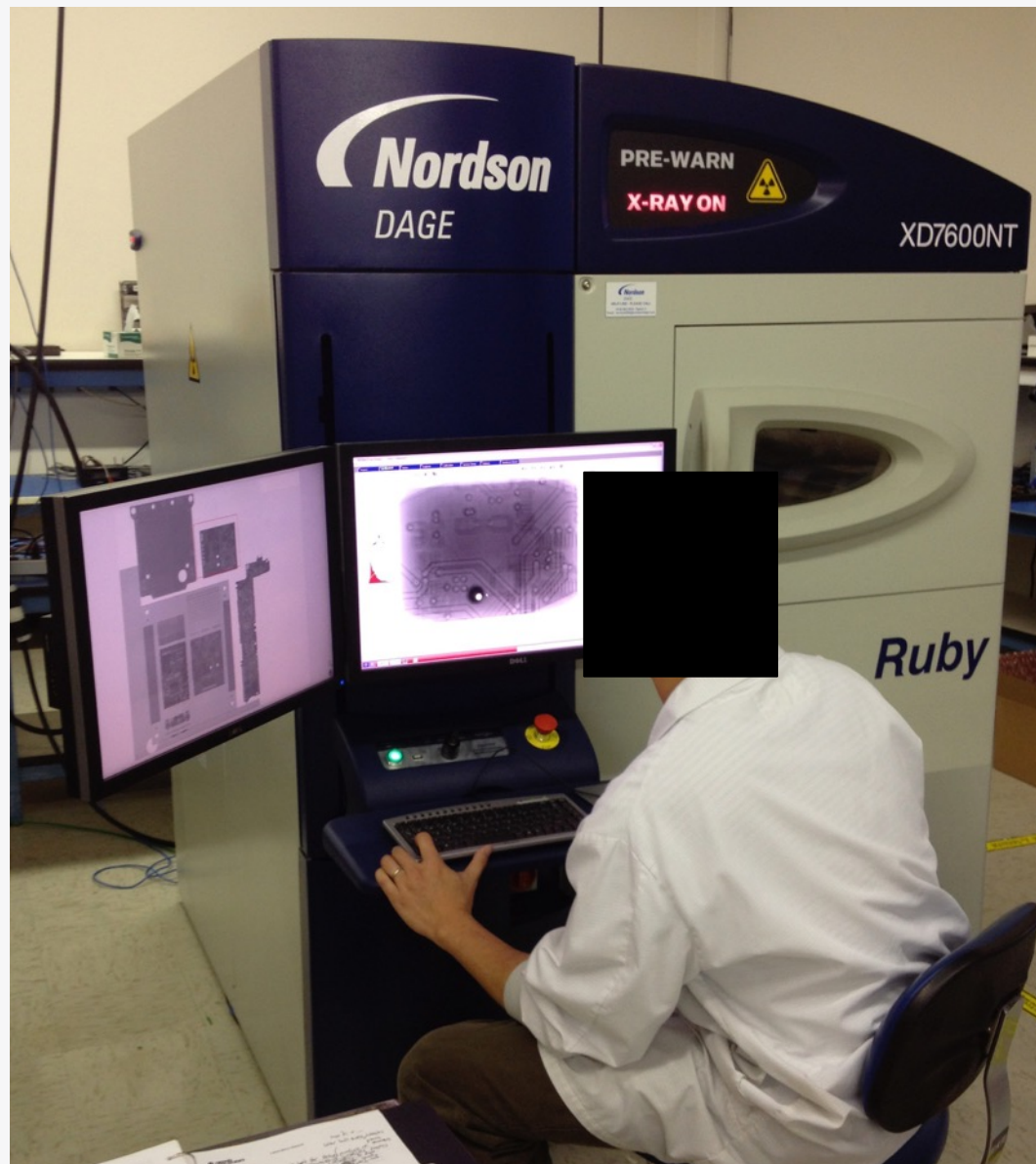
Imaging: X-Ray (3D/CT)

- Computed Tomography (CT)
 - A series of 2D X-ray images post-processed to create cross-sectional slices of the target
 - X-ray beam rotated 360° in a single axis around the target
- Typically used for complex inspection and failure analysis of PCBs, component packaging, solder ball/joint quality
- Acquisition
 - Capture a series of 2D X-ray images (60-720 depending on desired resolution)
- Reconstruction
 - Post-processing results in 2D slices that can be viewed in any plane (X, Y, Z)
 - Can be manipulated with 3D modeling software



Imaging: X-Ray (3D/CT) 2

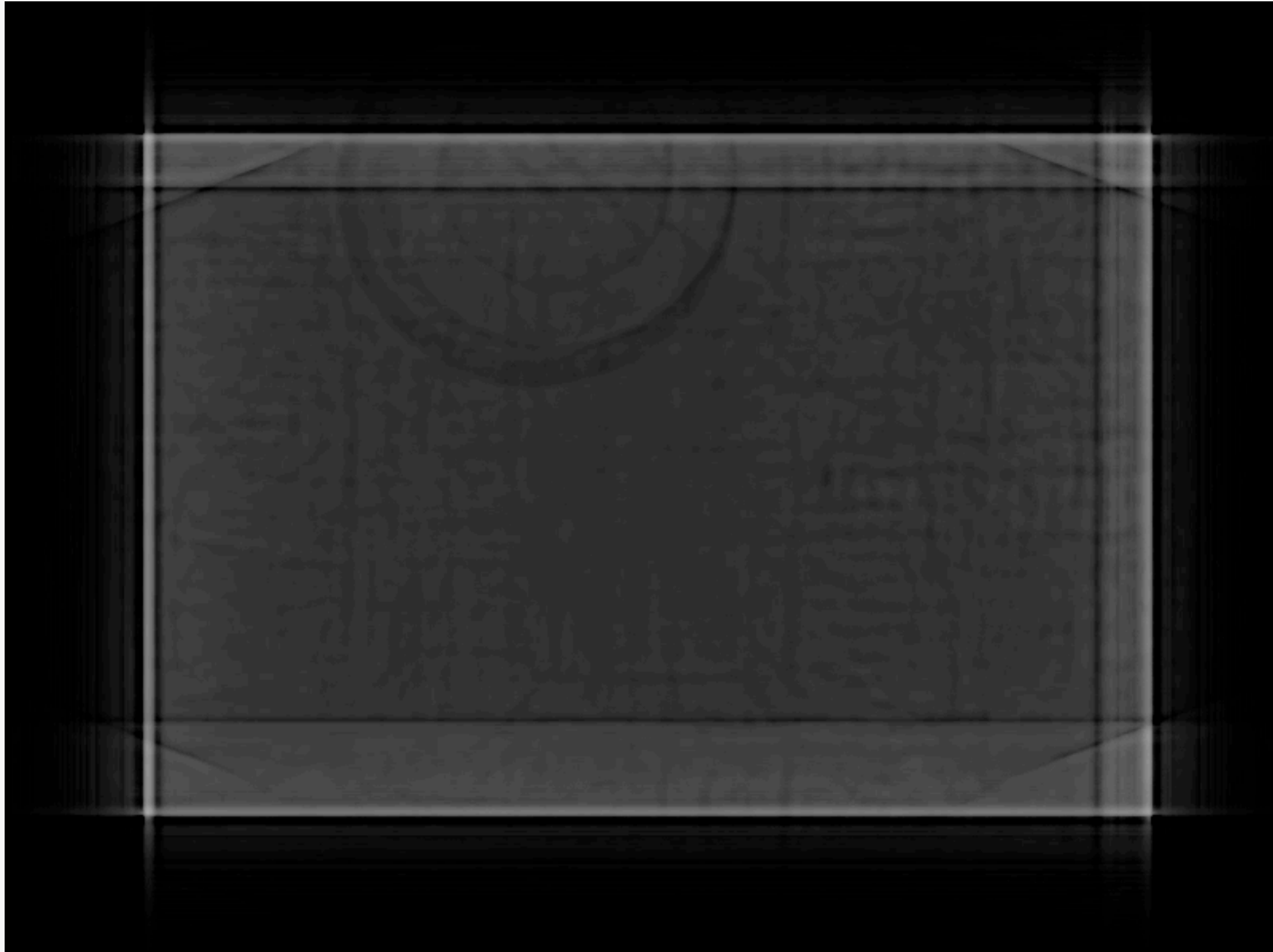
- Nordson DAGE XD7600NT Ruby X-ray Inspection System w/ X-Plane option @ Datest, Fremont, CA



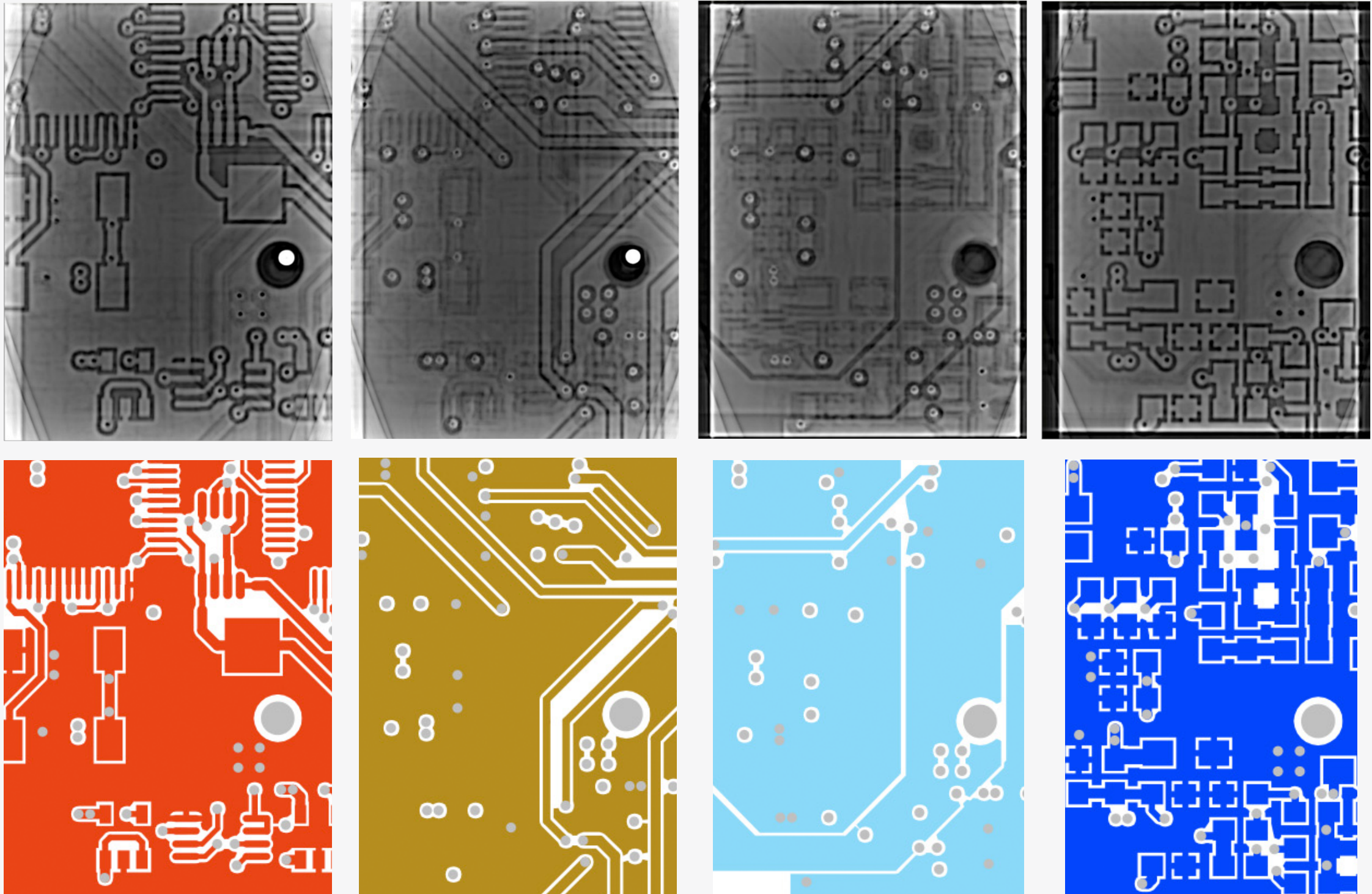
Imaging: X-Ray (3D/CT) 3

- Emic 2 Text-to-Speech Module
- 360 2D images taken at a 50° inclination angle
 - One image every 6 seconds
- Imported into VGStudio 2.1 for 3D model manipulation
- Manually moved through Z plane (top to bottom) to identify each layer
 - Could also measure substrate thickness between layers
 - Limited field-of-view will require multiple "segments" to be stitched together if working on a full PCB
- Results may vary based on layer count, inter-layer thickness, copper weight, substrate composition

Imaging: X-Ray (3D/CT) 4



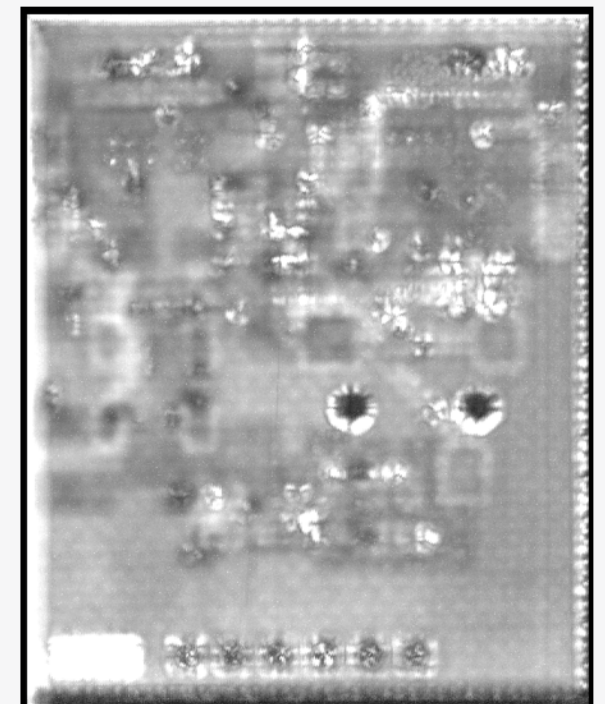
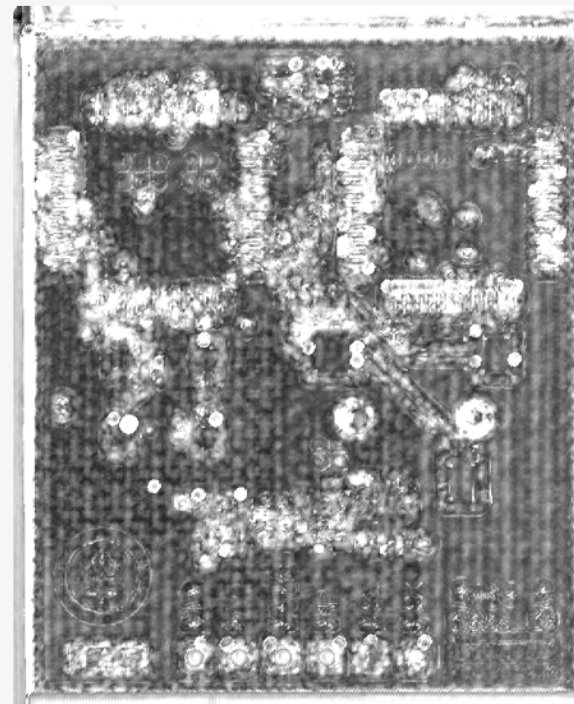
Imaging: X-Ray (3D/CT) 5



Emic 2 Text-to-Speech Module (5/8" x 7/8" area)

Imaging: Failures

- Acoustic Microscopy



Characterization Matrix

| Technique | Time | Cost | Accessibility | Ease of Use | Success Rate | Quality |
|----------------------------|------|--------|---------------|-------------|--------------|-----------|
| Solder Mask Removal | | | | | | |
| Sandpaper | < 1h | \$ | Easy | Easy | Fair | Good |
| Fiberglass scratch brush | < 1h | \$ | Easy | Easy | Excellent | Excellent |
| Abrasive sand blasting | < 1h | \$\$ | Moderate | Medium | Fair | Good |
| Ristoff C-8 | 3-4h | \$\$ | Difficult | Hard | Excellent | Excellent |
| MagnaStrip 500 | 3-4h | \$ | Difficult | Hard | Excellent | Excellent |
| Laser | 2-3h | \$\$\$ | Moderate | Hard | Varies | Excellent |
| Delaying | | | | | | |
| Sandpaper | 2-3h | \$ | Easy | Easy | Fair | Excellent |
| Dremel tool | < 1h | \$ | Easy | Medium | Poor | Varies |
| CNC milling | 3-4h | \$\$ | Moderate | Hard | Excellent | Excellent |
| Surface grinding | 3-4h | \$\$\$ | Moderate | Hard | Excellent | Excellent |
| Imaging | | | | | | |
| Infrared (IR) | < 1h | \$ | Easy | Easy | Excellent | Good |
| X-ray (2D) | Many | \$\$\$ | Moderate | Medium | Poor | Varies |
| Computerized Tomography | 1-2h | \$\$\$ | Moderate | Medium | Fair | Excellent |

The End.

